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**Keller et al.**

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(54) **EMITTER PACKAGE**

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(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/180**

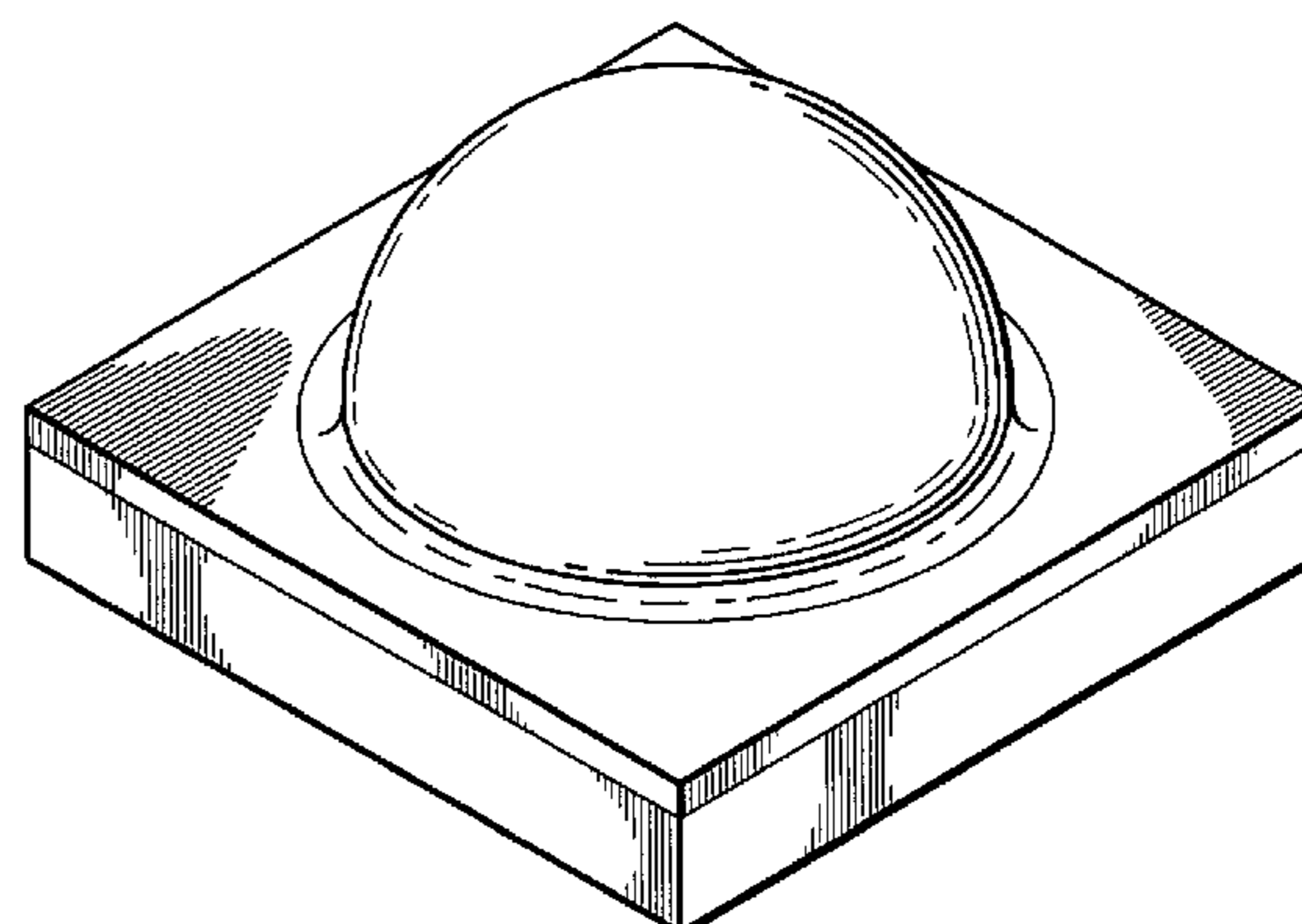
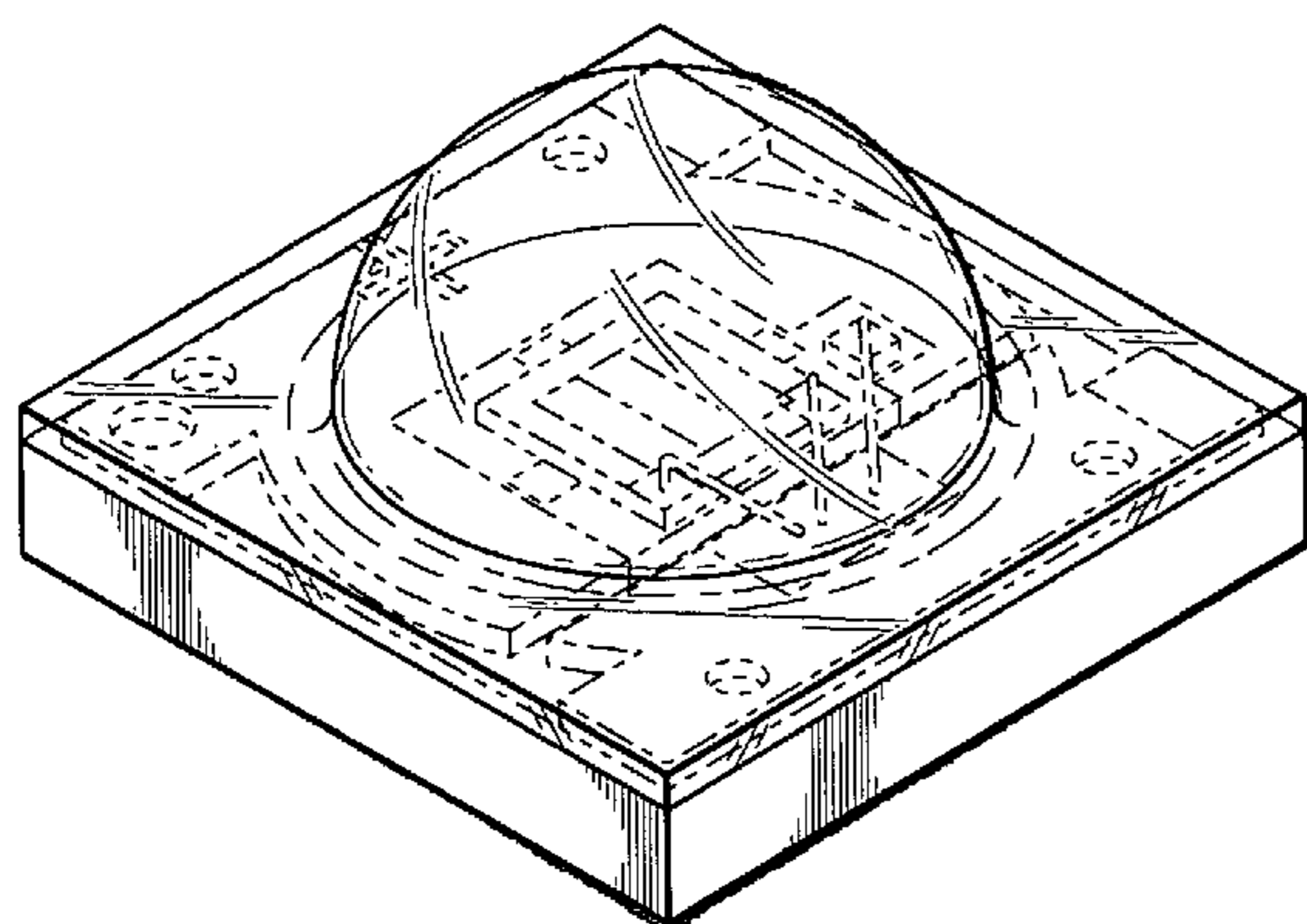
(58) **Field of Classification Search** ..... D13/180;  
D26/2; 257/79, 80, 81, 88, 89, 95, 98, 99,  
257/100; 313/483, 498, 500; 362/555, 800  
See application file for complete search history.

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*Primary Examiner*—Selina Sikder  
 (74) *Attorney, Agent, or Firm*—Koppel, Patrick, Heybl & Dawson

(57) **CLAIM**

The ornamental design for an emitter package, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of the first embodiment of an emitter package showing our design;

FIG. 2 is a top plan view of the emitter package shown in FIG. 1;

FIG. 3 is a bottom plan view of the emitter package shown in FIG. 1;

FIG. 4 is front elevation view of the emitter package shown in FIG. 1, with the back elevation view being a mirror image thereof;

FIG. 5 is a right side elevation view of the emitter package shown in FIG. 1, with the left side elevation view being a mirror image thereof;

FIG. 6 is a bottom perspective view of the emitter package shown in FIG. 1;

FIG. 7 is a top perspective view of the second embodiment of an emitter package showing our design;

FIG. 8 is a top plan view of the emitter package shown in FIG. 7;

FIG. 9 is a bottom plan view of the emitter package shown in FIG. 7;

FIG. 10 is front elevation view of the emitter package shown in FIG. 7, with the back elevation view being a mirror thereof;

FIG. 11 is a right side elevation view of the emitter package shown in FIG. 7, with the left side elevation view being a mirror image thereof;

FIG. 12 is a bottom perspective view of the emitter package shown in FIG. 7;

FIG. 13 is a perspective view of the third embodiment of an emitter package showing our design;

FIG. 14 is a top plan view of the emitter package shown in FIG. 13;

FIG. 15 is a bottom plan view of the emitter package shown in FIG. 13;

FIG. 16 is front elevation view of the emitter package shown in FIG. 13, with the back elevation view being a mirror image thereof;

FIG. 17 is a right side elevation view of the emitter package shown in FIG. 13, with the left side elevation view being a mirror image thereof;

FIG. 18 is a bottom perspective view of the emitter package shown in FIG. 13;

FIG. 19 is a perspective view of the fourth embodiment of an emitter package showing our design;

FIG. 20 is a top plan view of the emitter package shown in FIG. 19;

FIG. 21 is a bottom plan view of the emitter package shown in FIG. 19;

FIG. 22 is front elevation view of the emitter package shown in FIG. 19, with the back elevation view being a mirror image thereof;

FIG. 23 is a right side elevation view of the emitter package shown in FIG. 19, with the left side elevation view being a mirror image thereof;

FIG. 24 is a bottom perspective view of the emitter package shown in FIG. 19;

FIG. 25 is a perspective view of the fifth embodiment of an emitter package showing our design;

FIG. 26 is a top plan view of the emitter package shown in FIG. 25;

FIG. 27 is a bottom plan view of the emitter package shown in FIG. 25;

FIG. 28 is front elevation view of the emitter package shown in FIG. 25, with the back elevation view being a mirror image thereof;

FIG. 29 is a right side elevation view of the emitter package shown in FIG. 25, with the left side elevation view being a mirror image thereof;

FIG. 30 is a bottom perspective view of the emitter package shown in FIG. 25;

FIG. 31 is a perspective view of the sixth embodiment of an emitter package showing our design;

FIG. 32 is a top plan view of the emitter package shown in FIG. 31;

FIG. 33 is a bottom plan view of the emitter package shown in FIG. 31;

FIG. 34 is front elevation view of the emitter package shown in FIG. 31, with the back elevation view being a mirror image thereof;

FIG. 35 is a right side elevation view of the emitter package shown in FIG. 31, with the left side elevation view being a mirror image thereof; and,

FIG. 36 is a bottom perspective view of the emitter package shown in FIG. 31.

The broken line showing in the embodiments of FIGS. 1-6, 13-18, 19-24 and 25-30 are for illustrative purposes only and forms no part of the claimed design. The external surface having stippling or irregular lines in the embodiments of FIGS. 25-30 and 31-36 indicate a rough visual appearance of the side surfaces of the emitter package. The top layer can have be visually transparent or translucent as shown in the embodiments of FIGS. 1-6, 13-18, 19-24 and 25-30, and in some embodiments can optically distort the layer below.

**1 Claim, 12 Drawing Sheets**

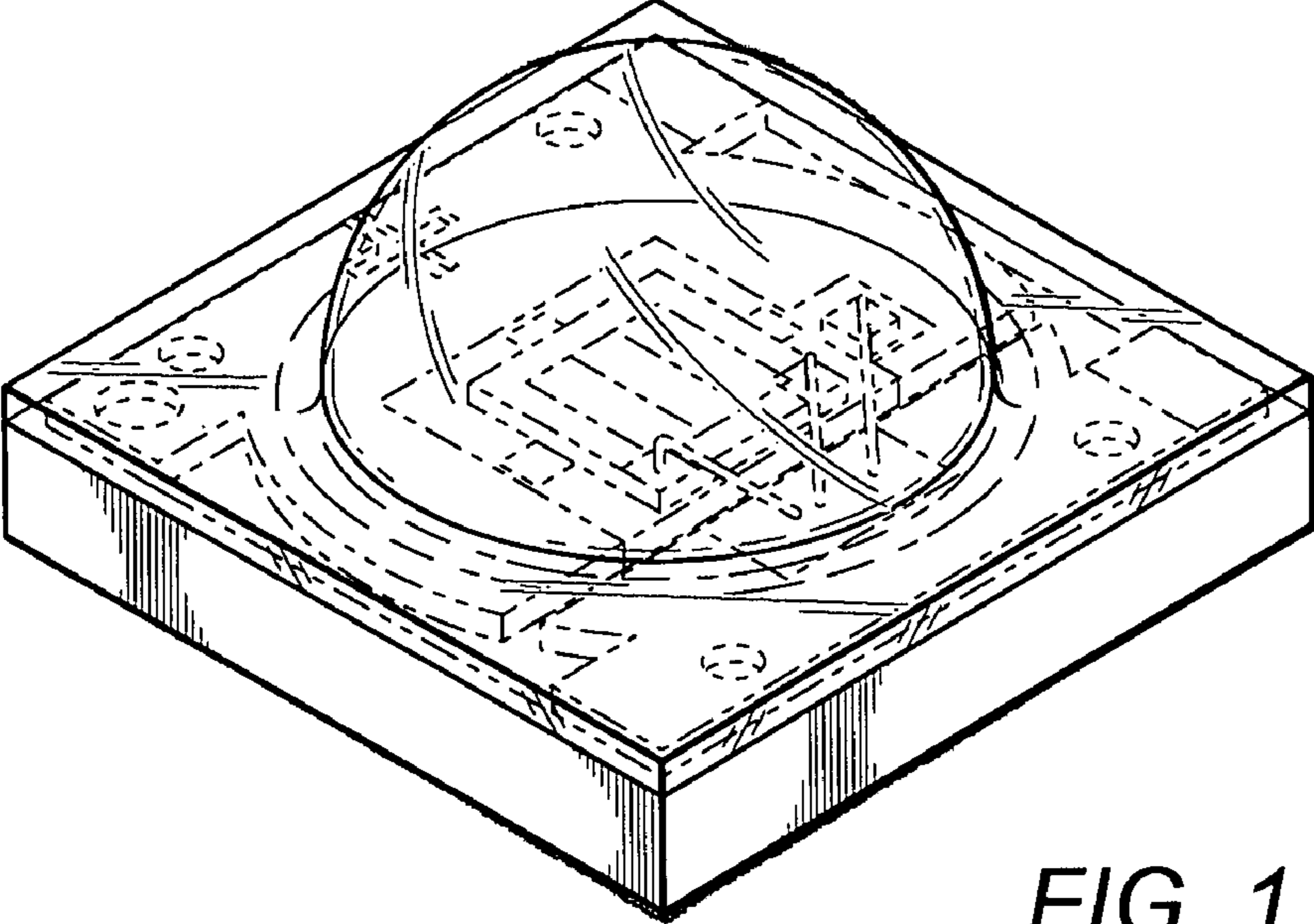


FIG. 1

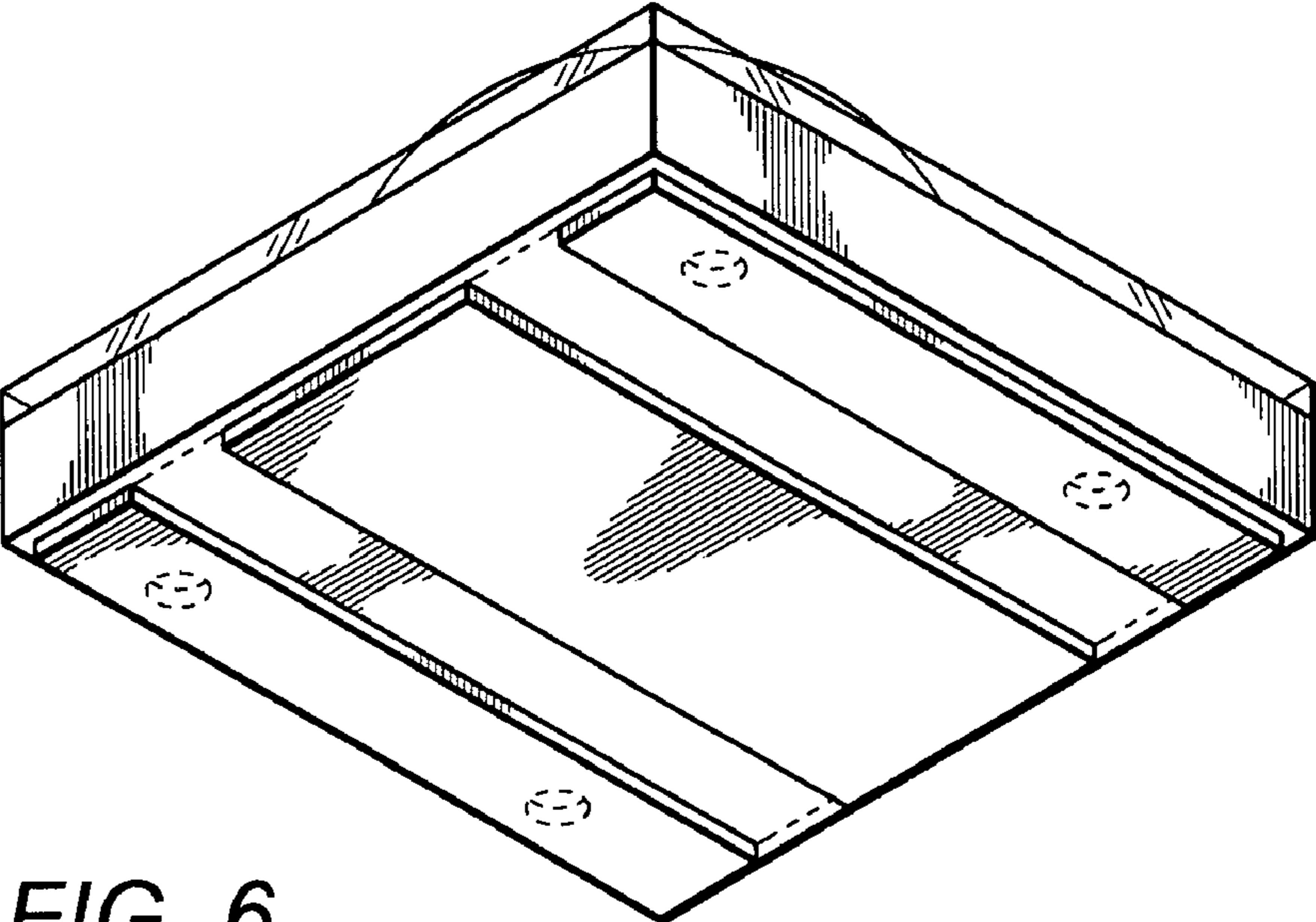
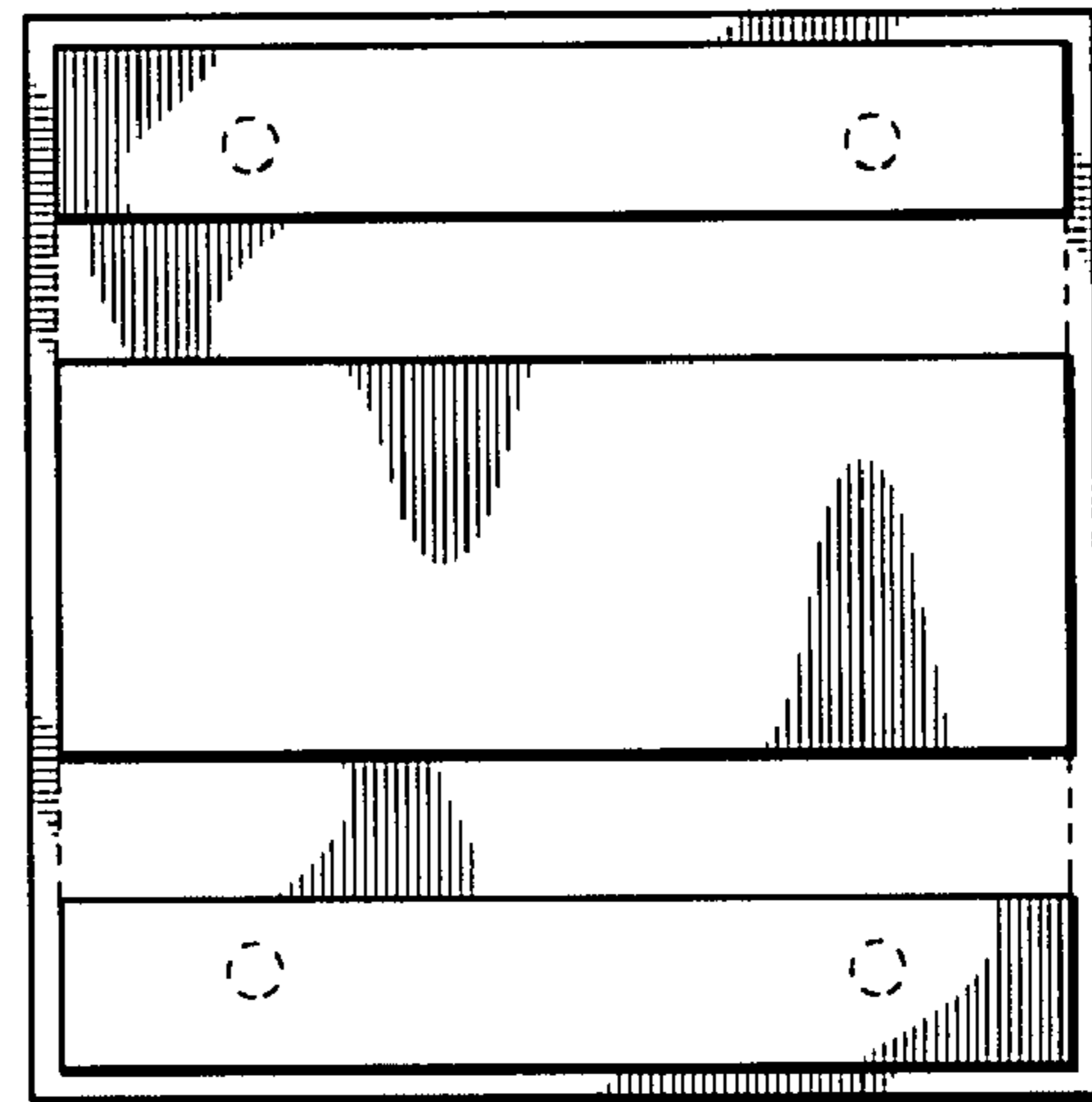
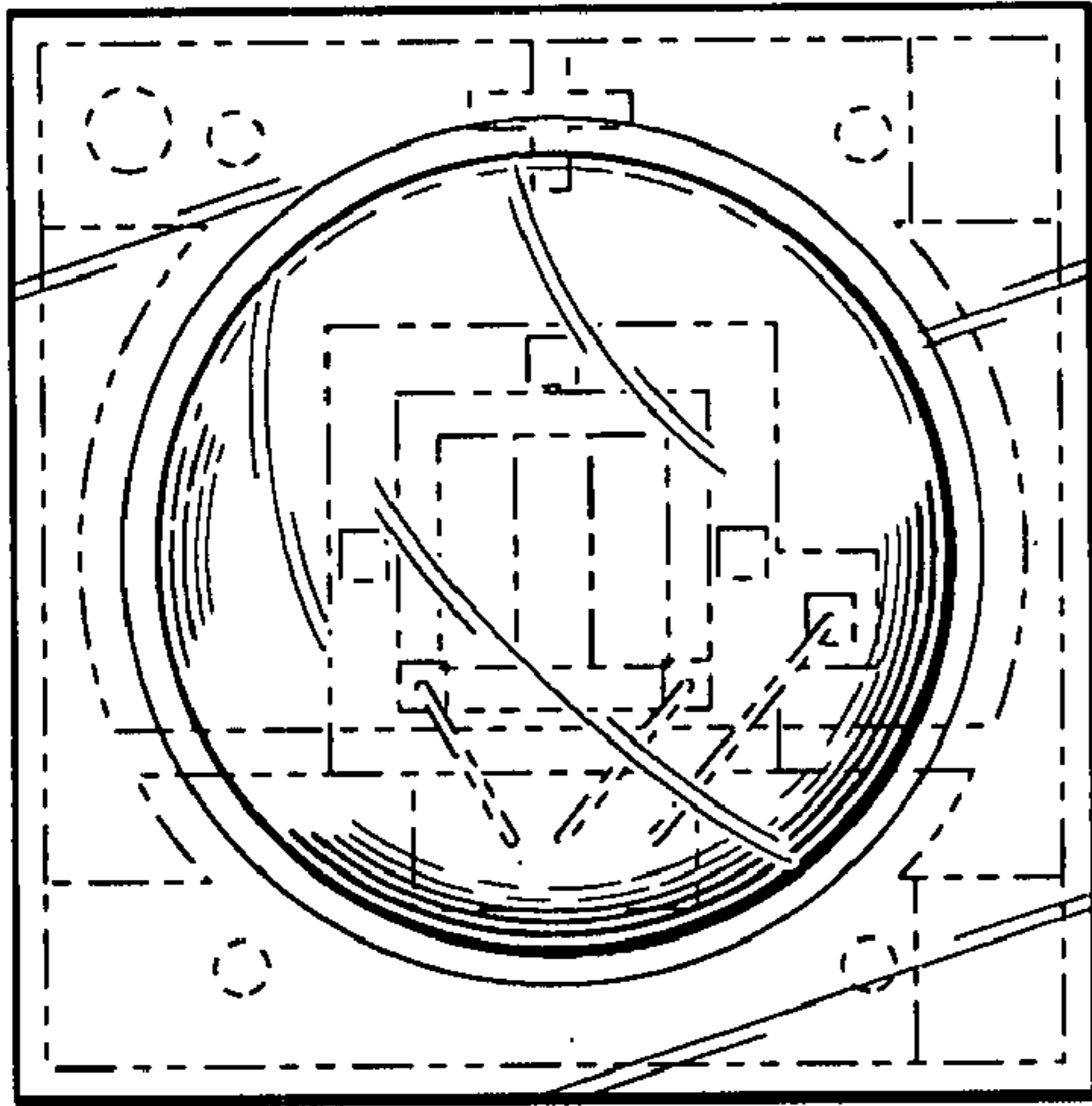
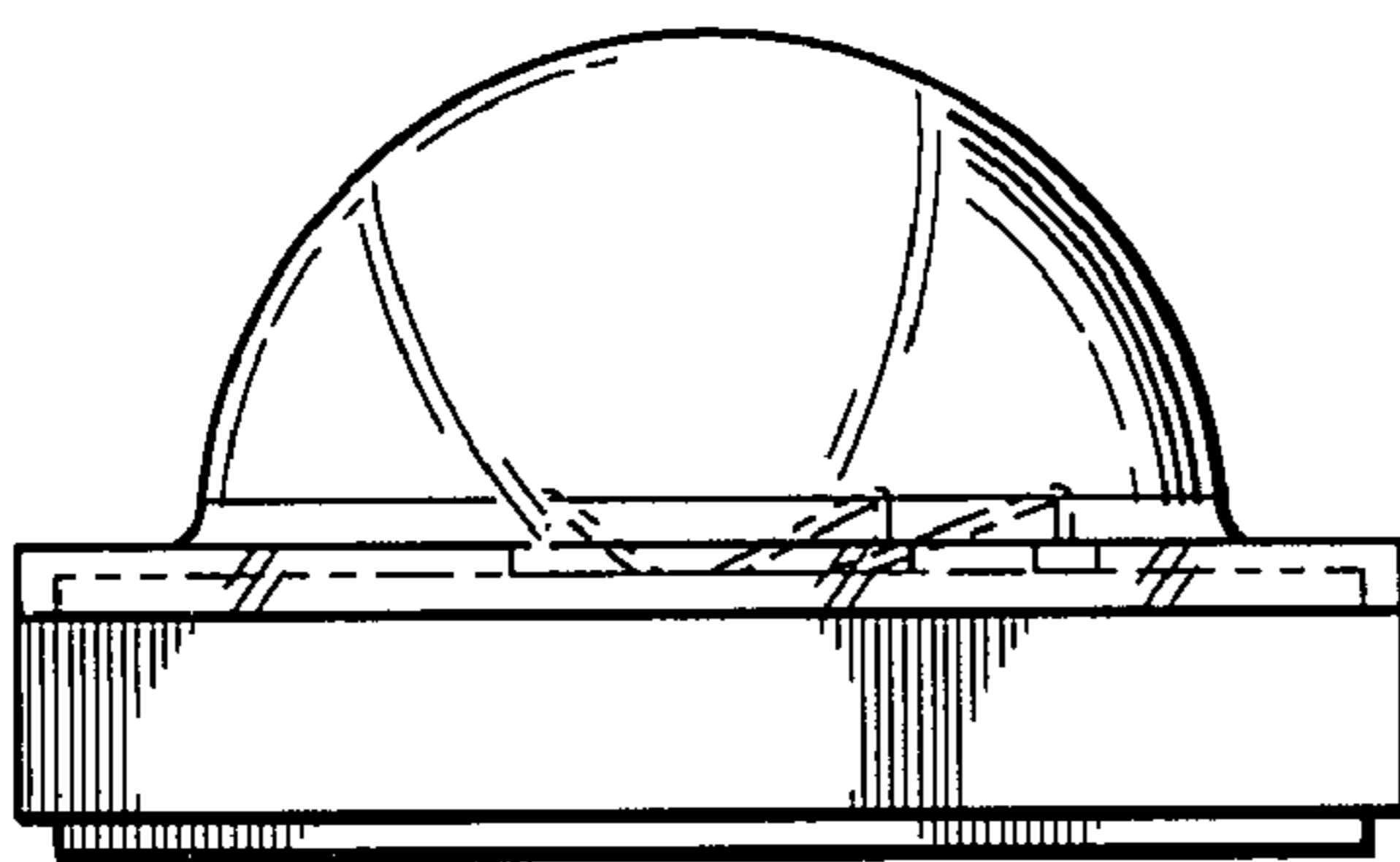


FIG. 6

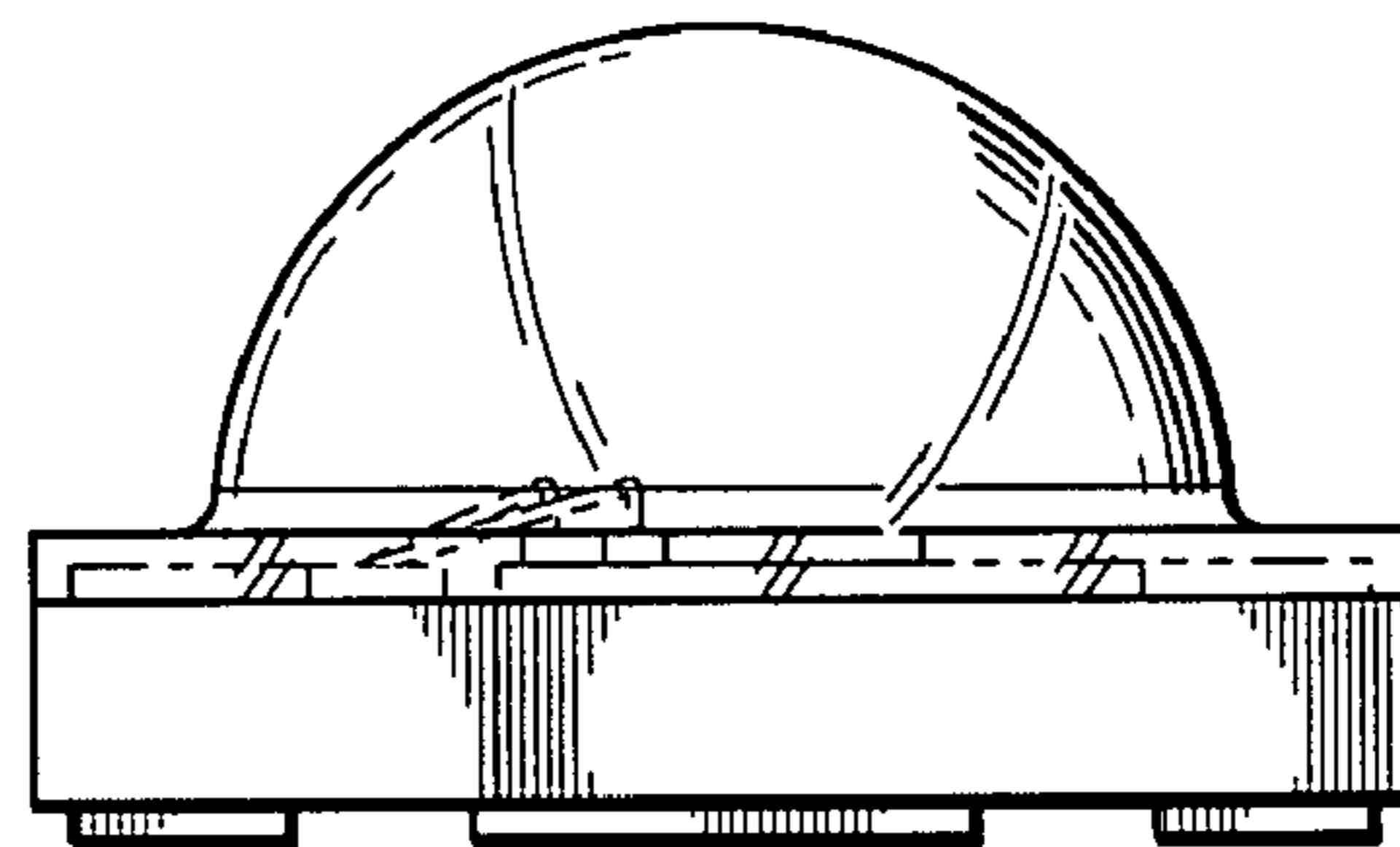
*FIG. 2*



*FIG. 3*



*FIG. 4*



*FIG. 5*

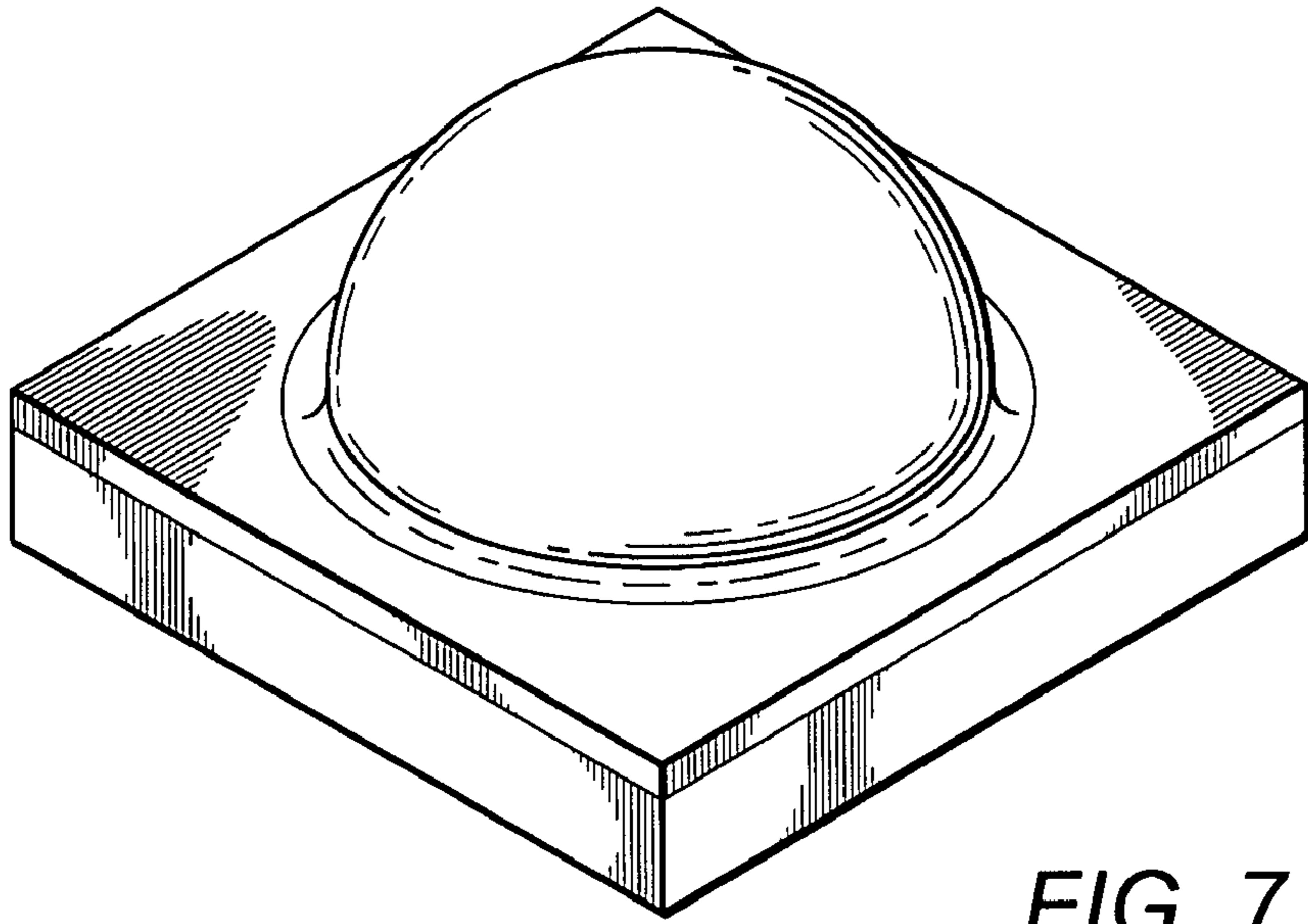


FIG. 7

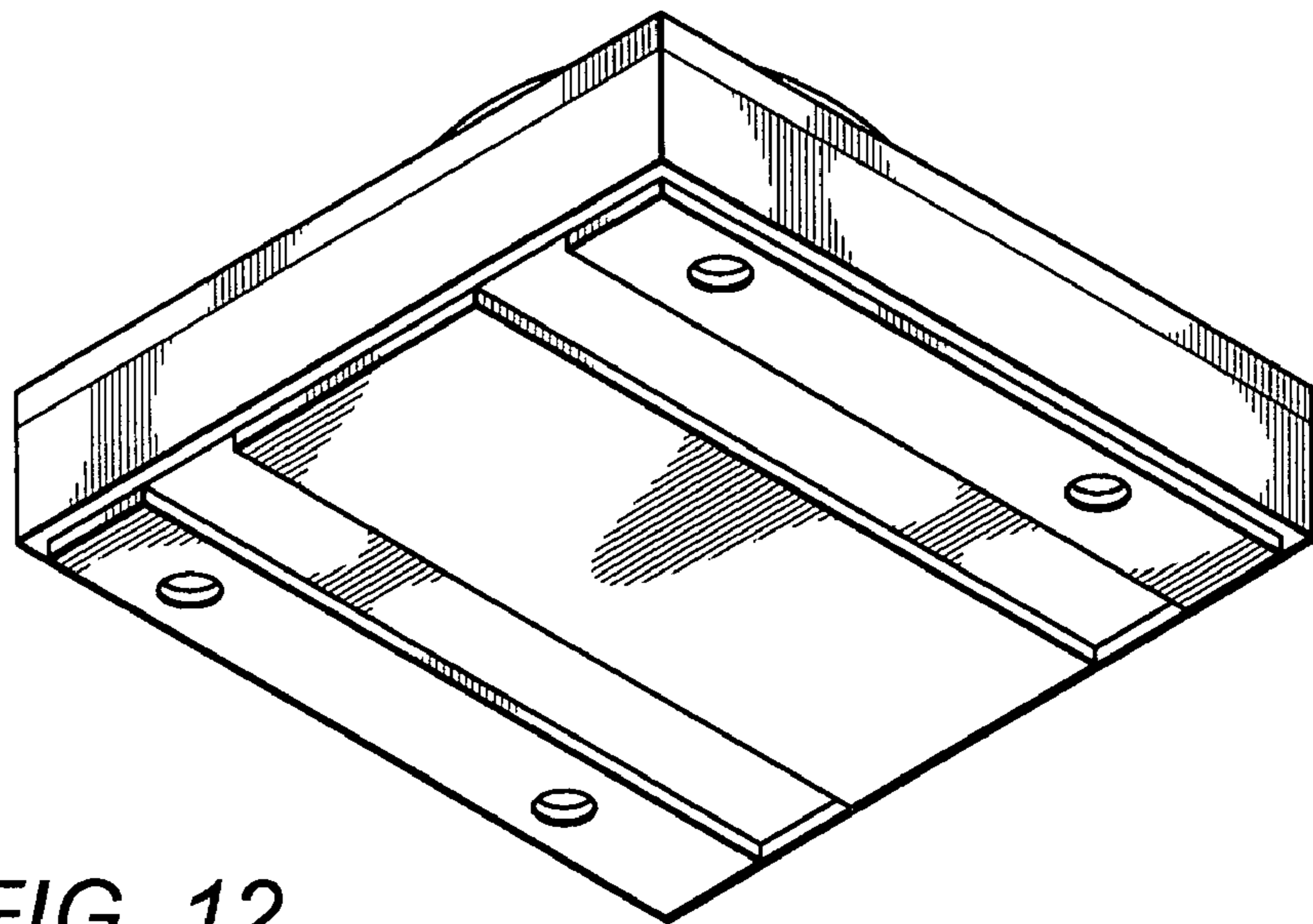
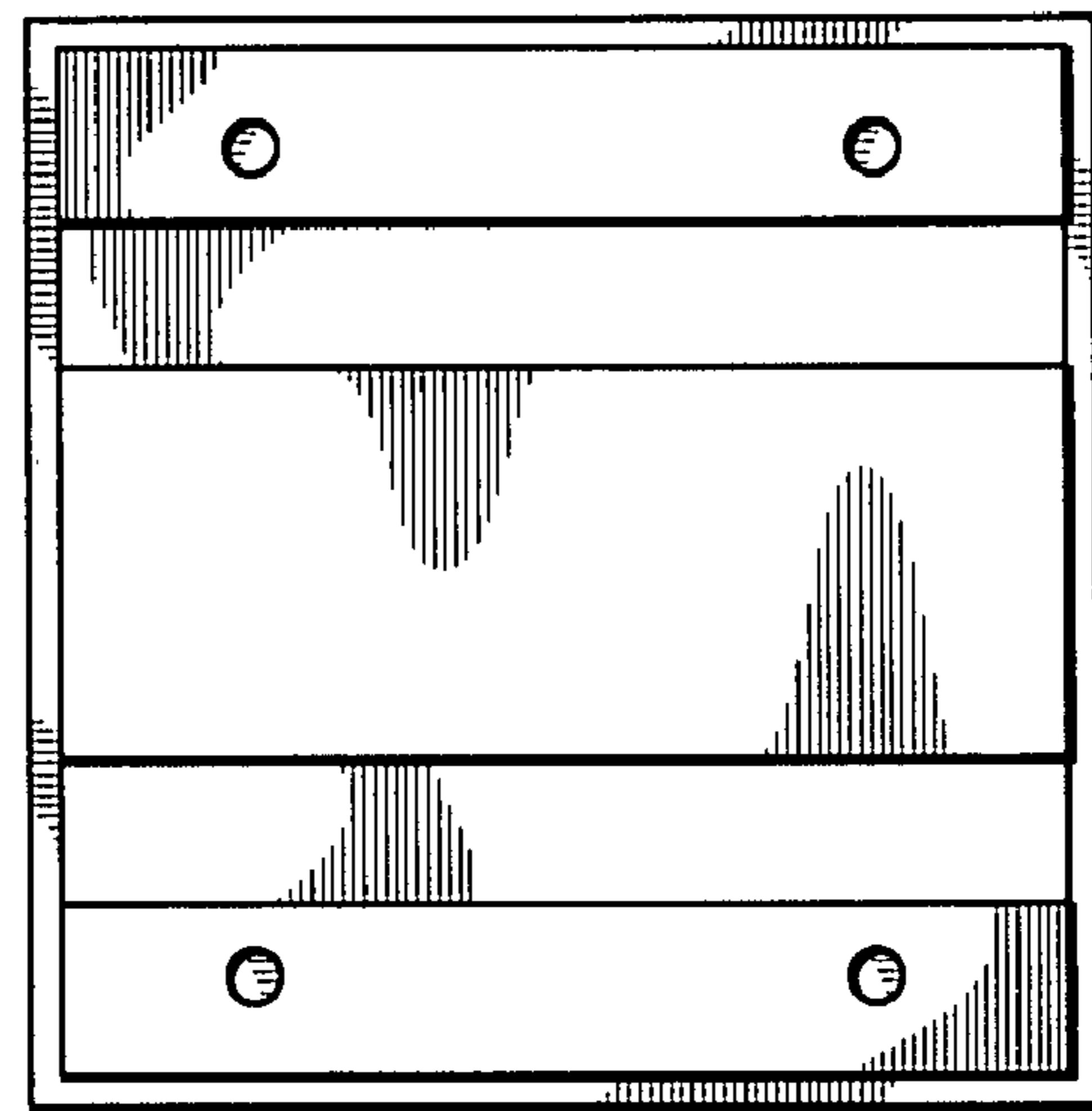
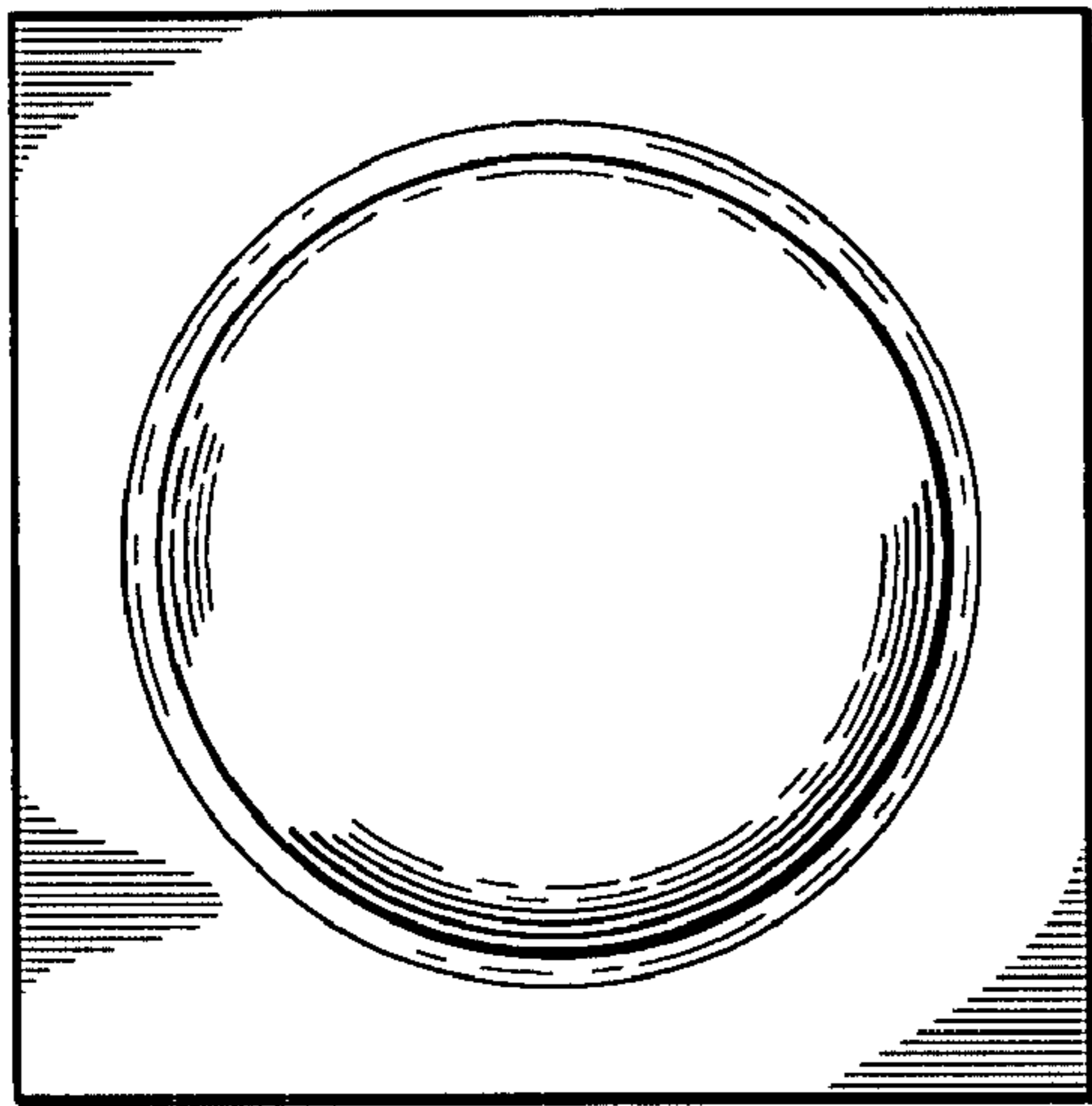
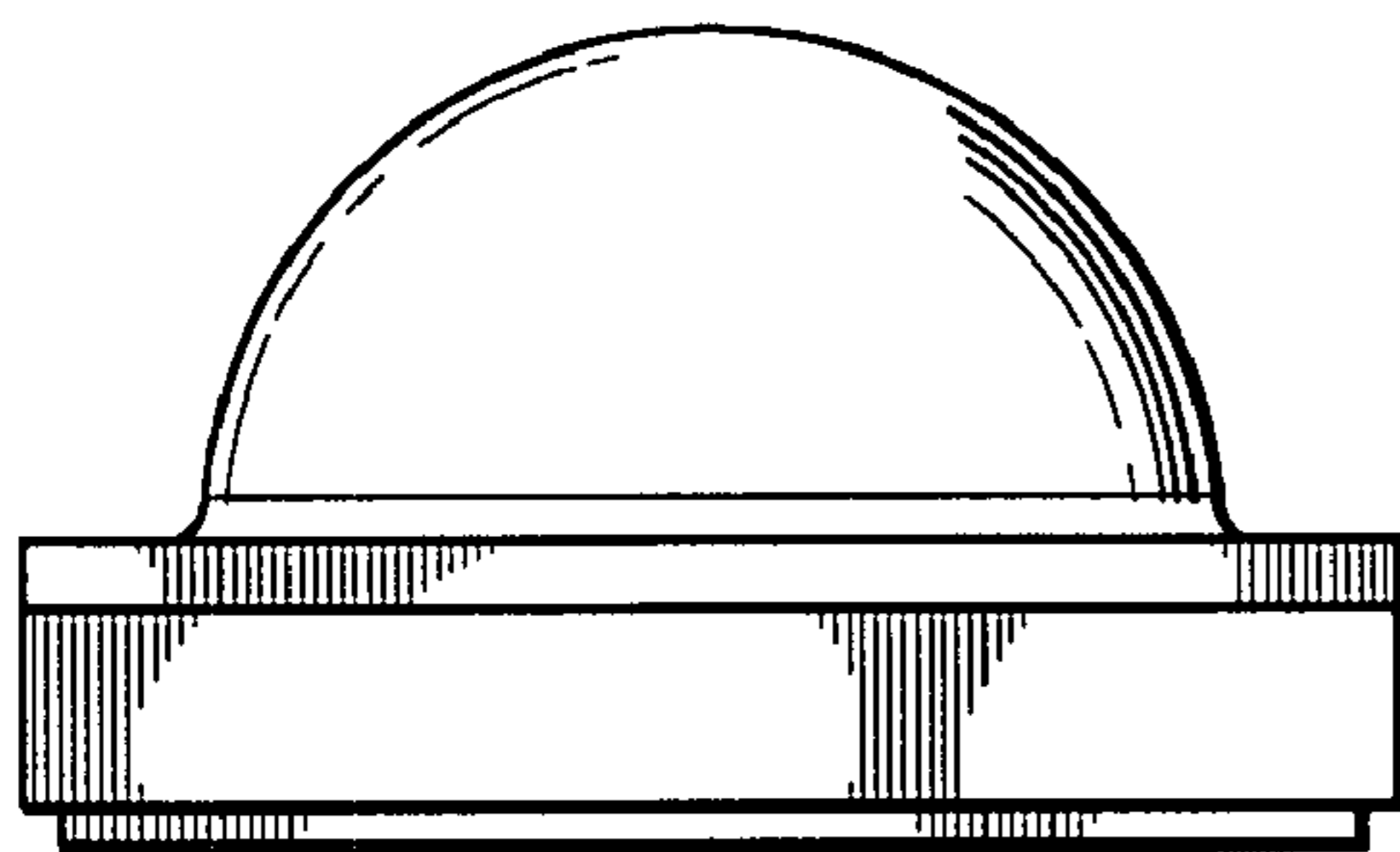


FIG. 12

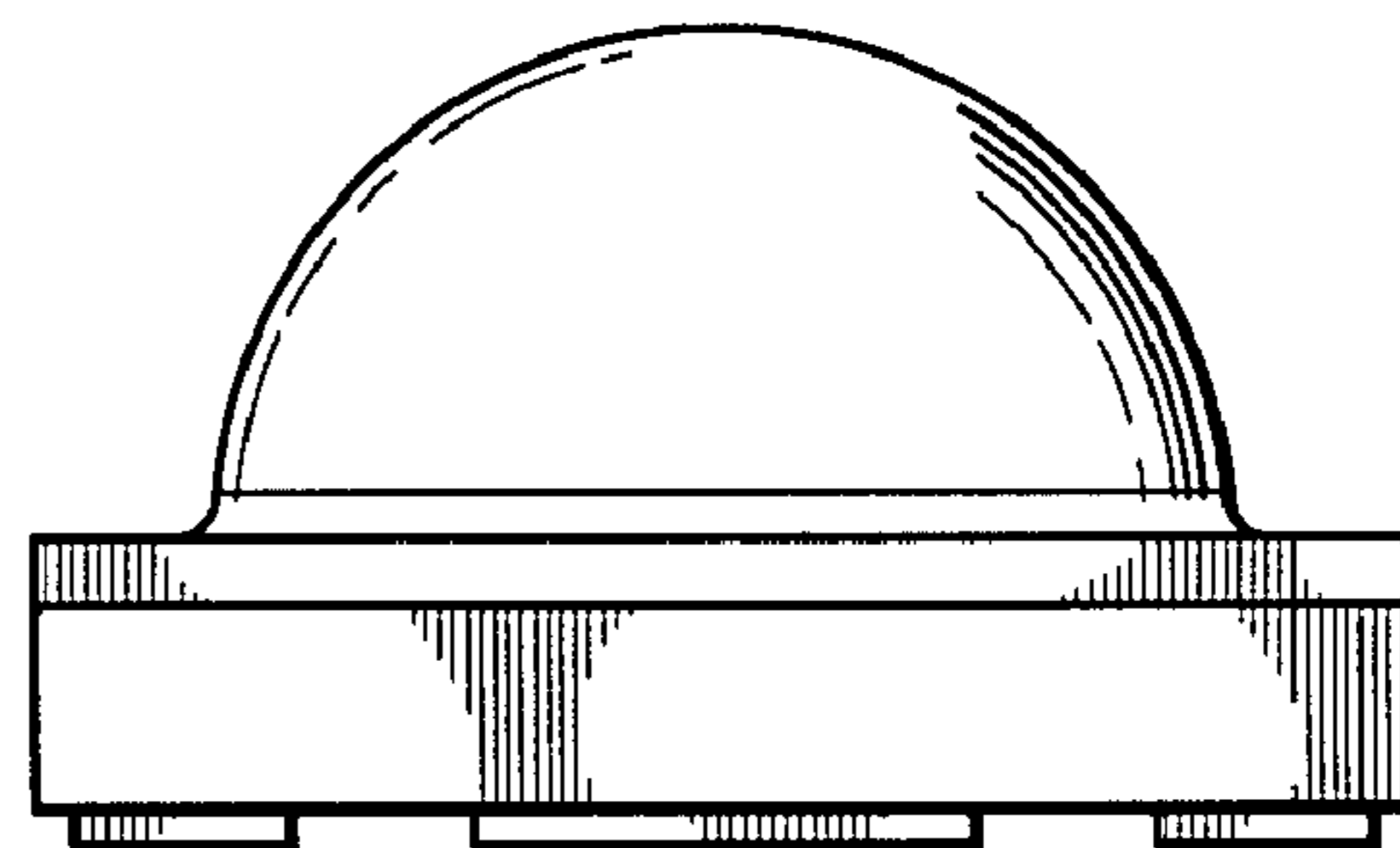
*FIG. 8*



*FIG. 9*



*FIG. 10*



*FIG. 11*

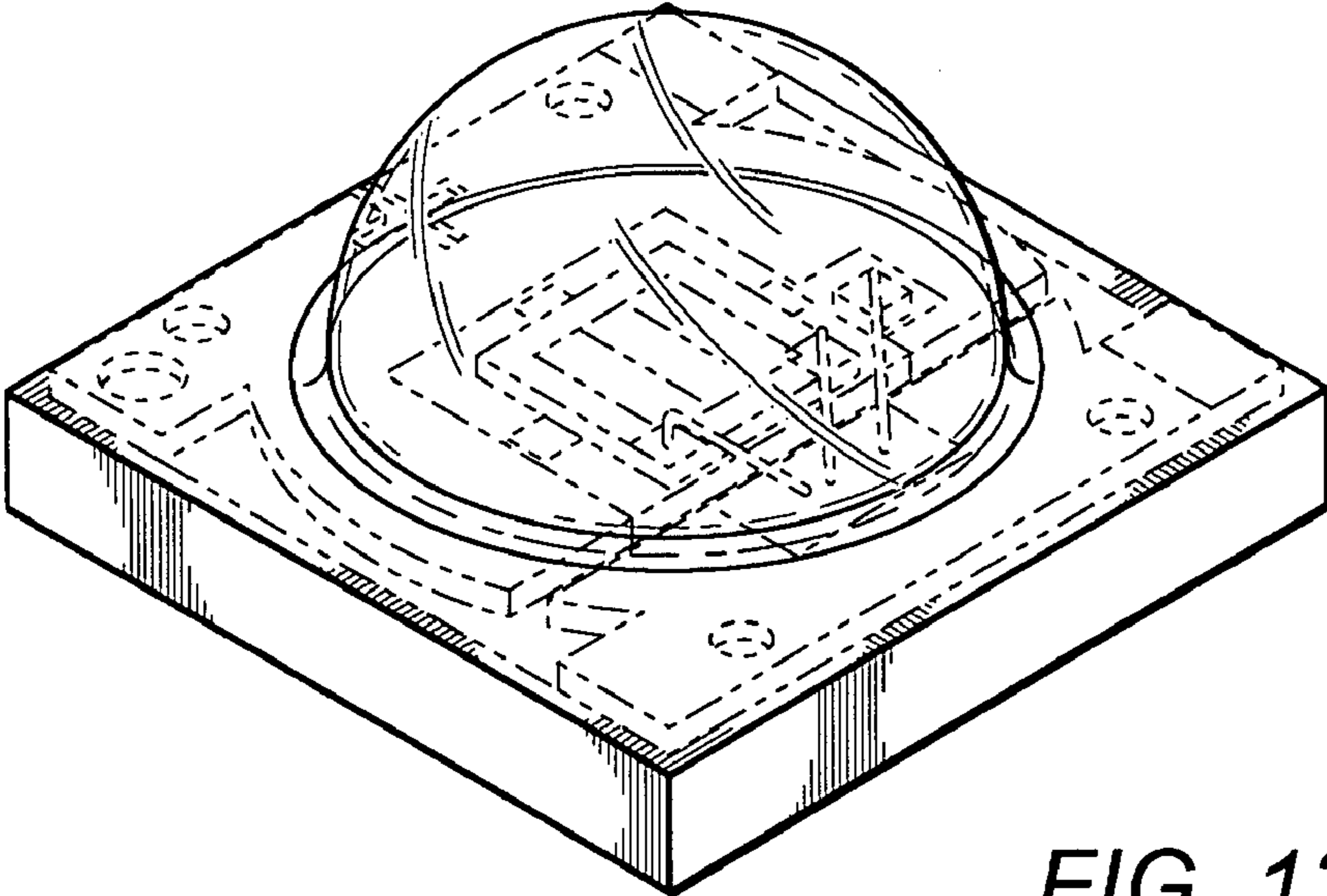


FIG. 13

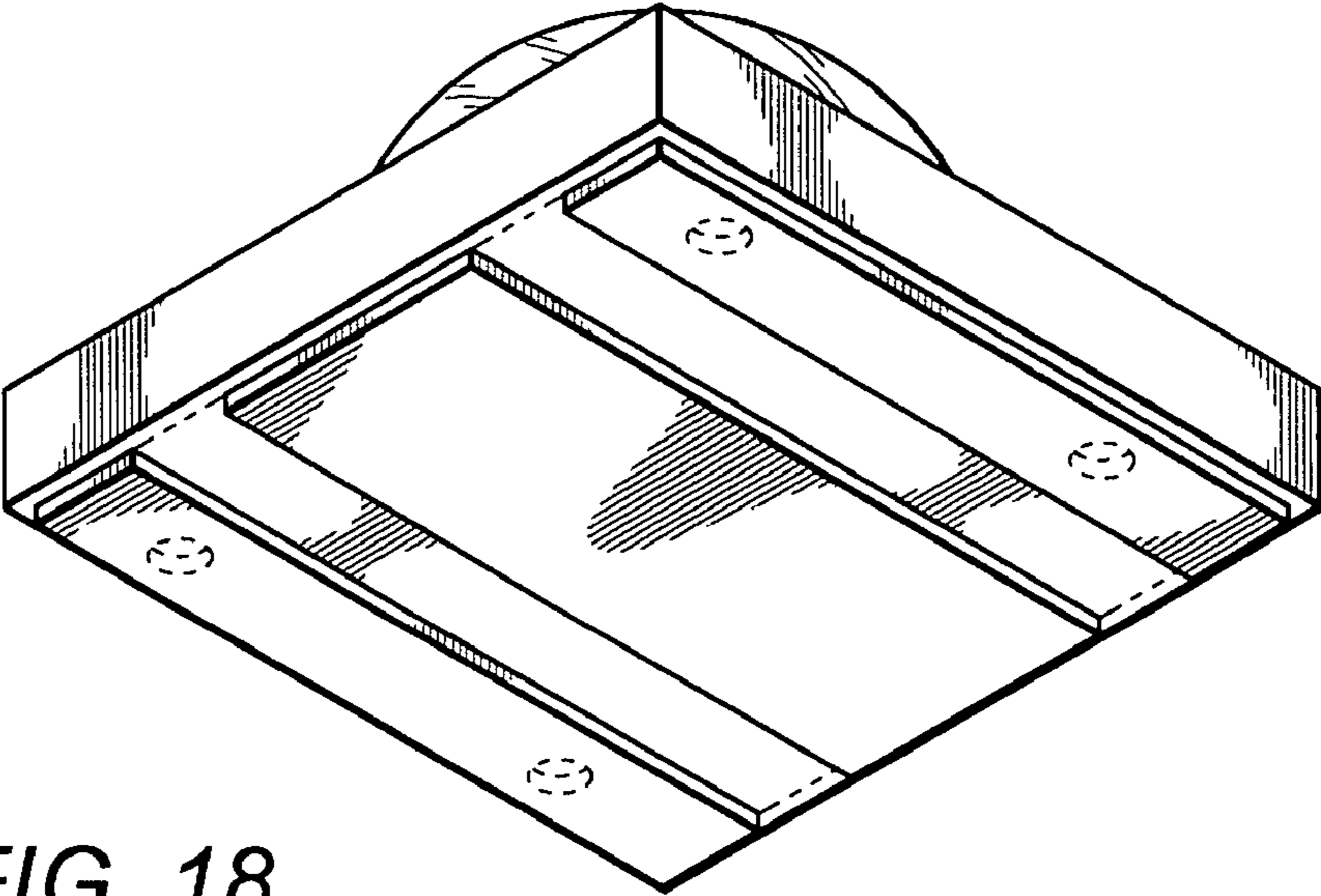
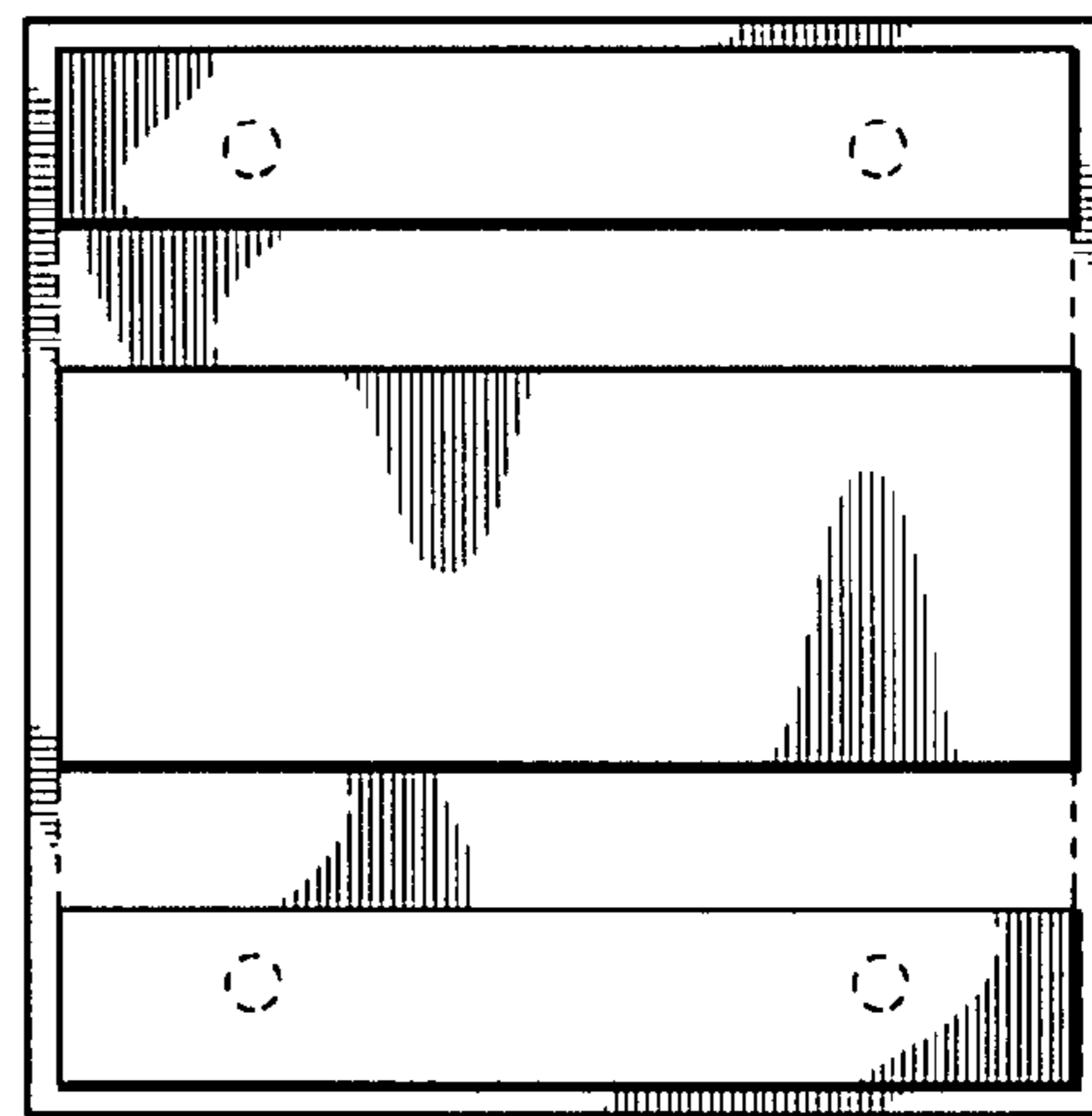
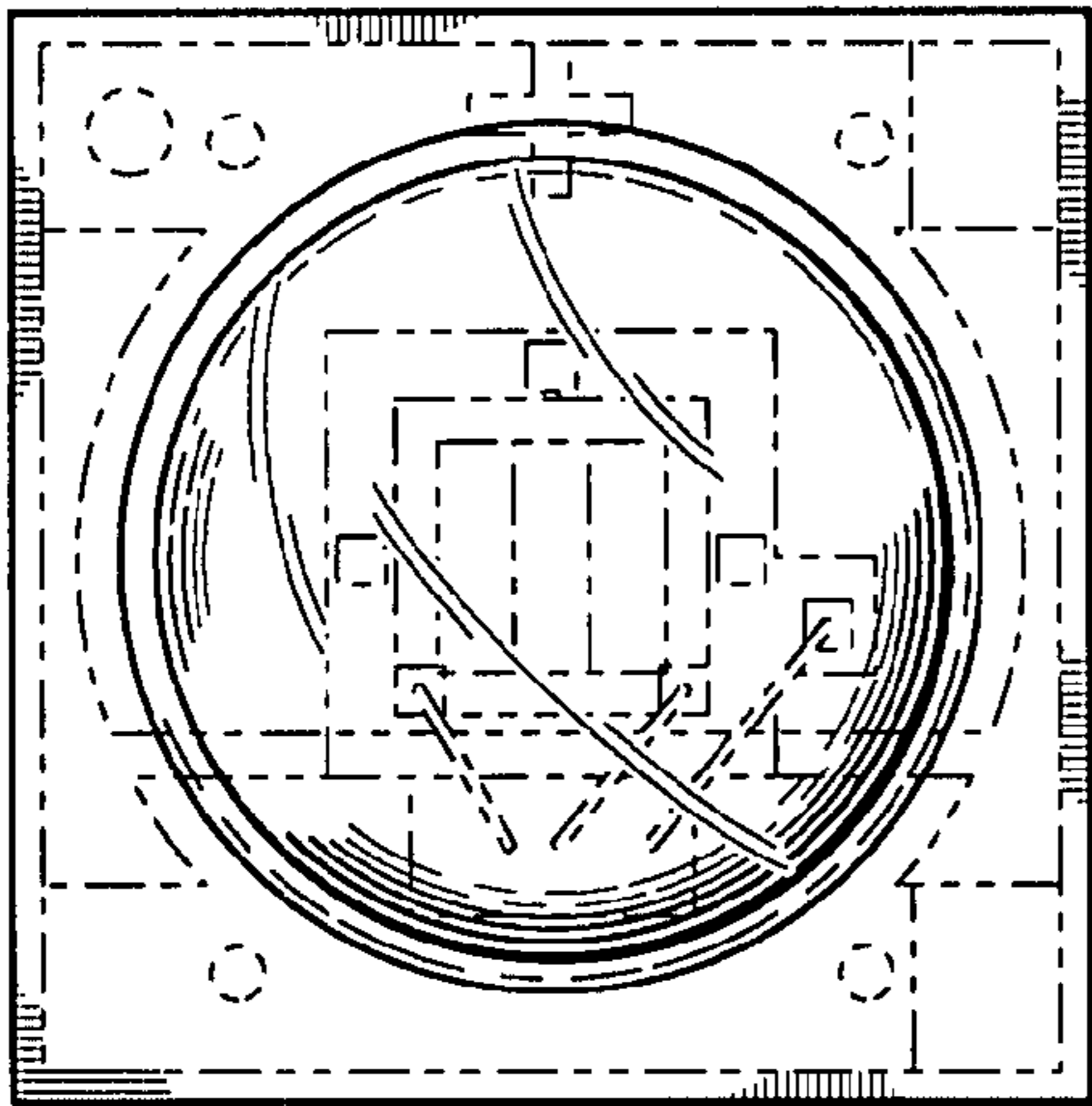


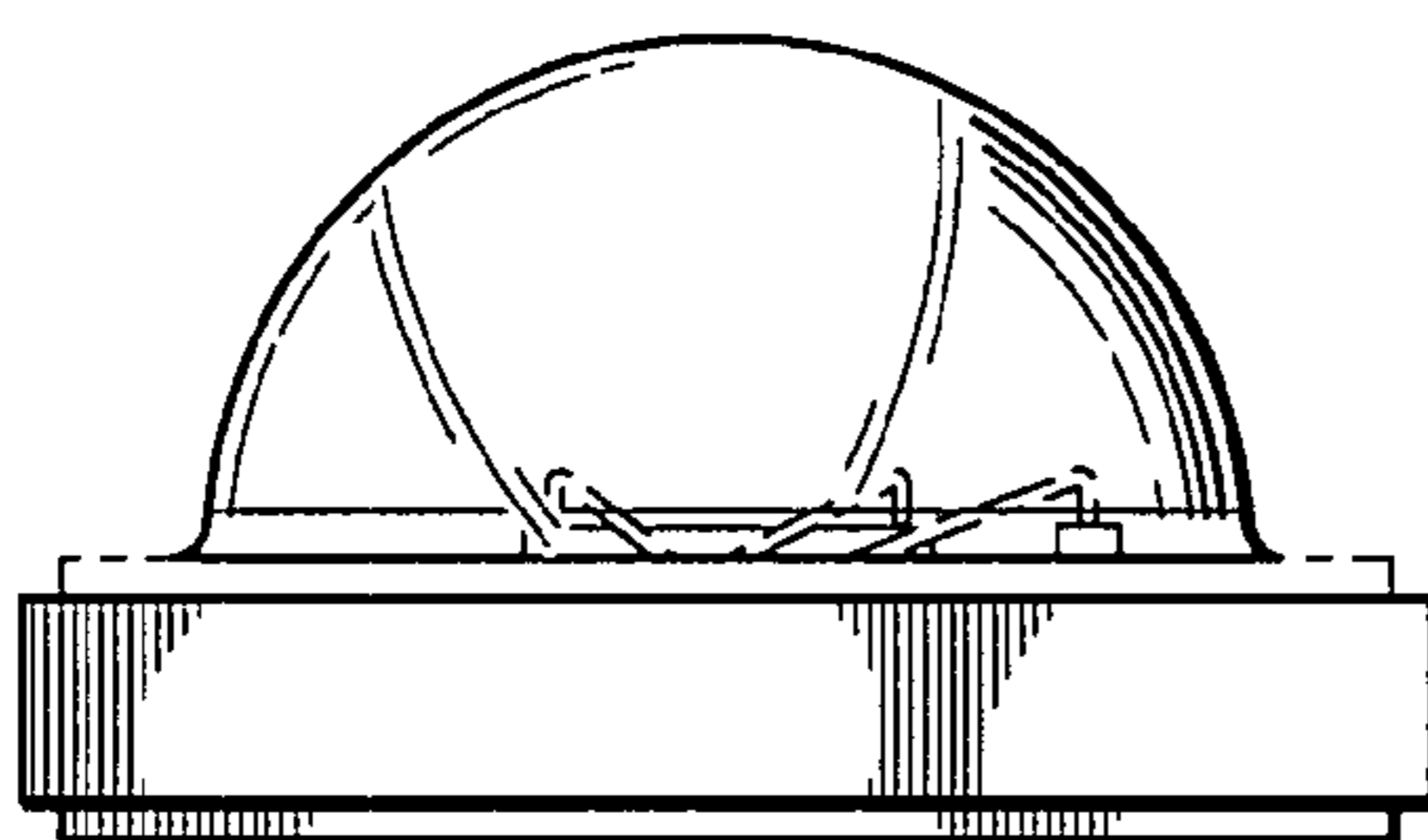
FIG. 18



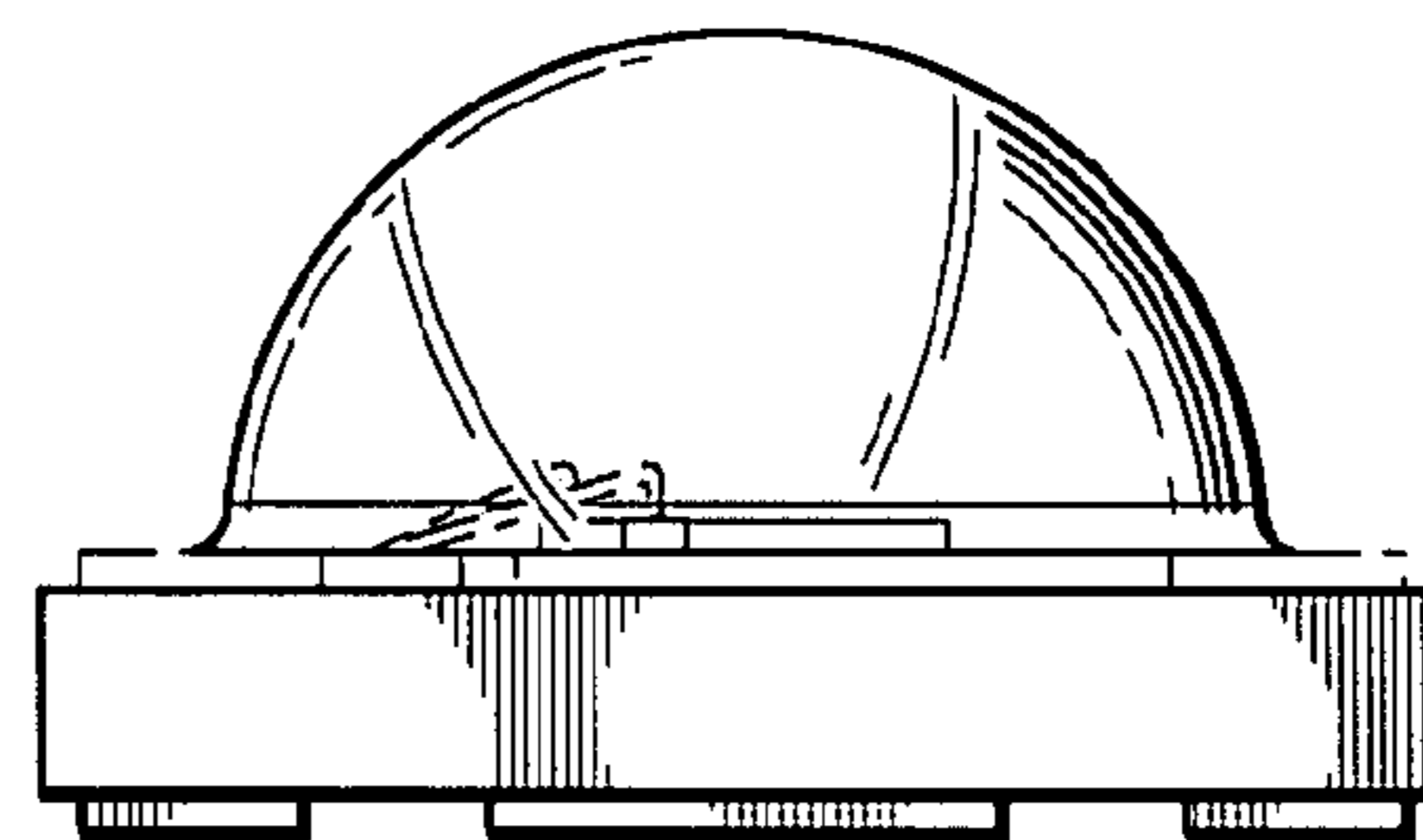
*FIG. 14*



*FIG. 15*



*FIG. 16*



*FIG. 17*

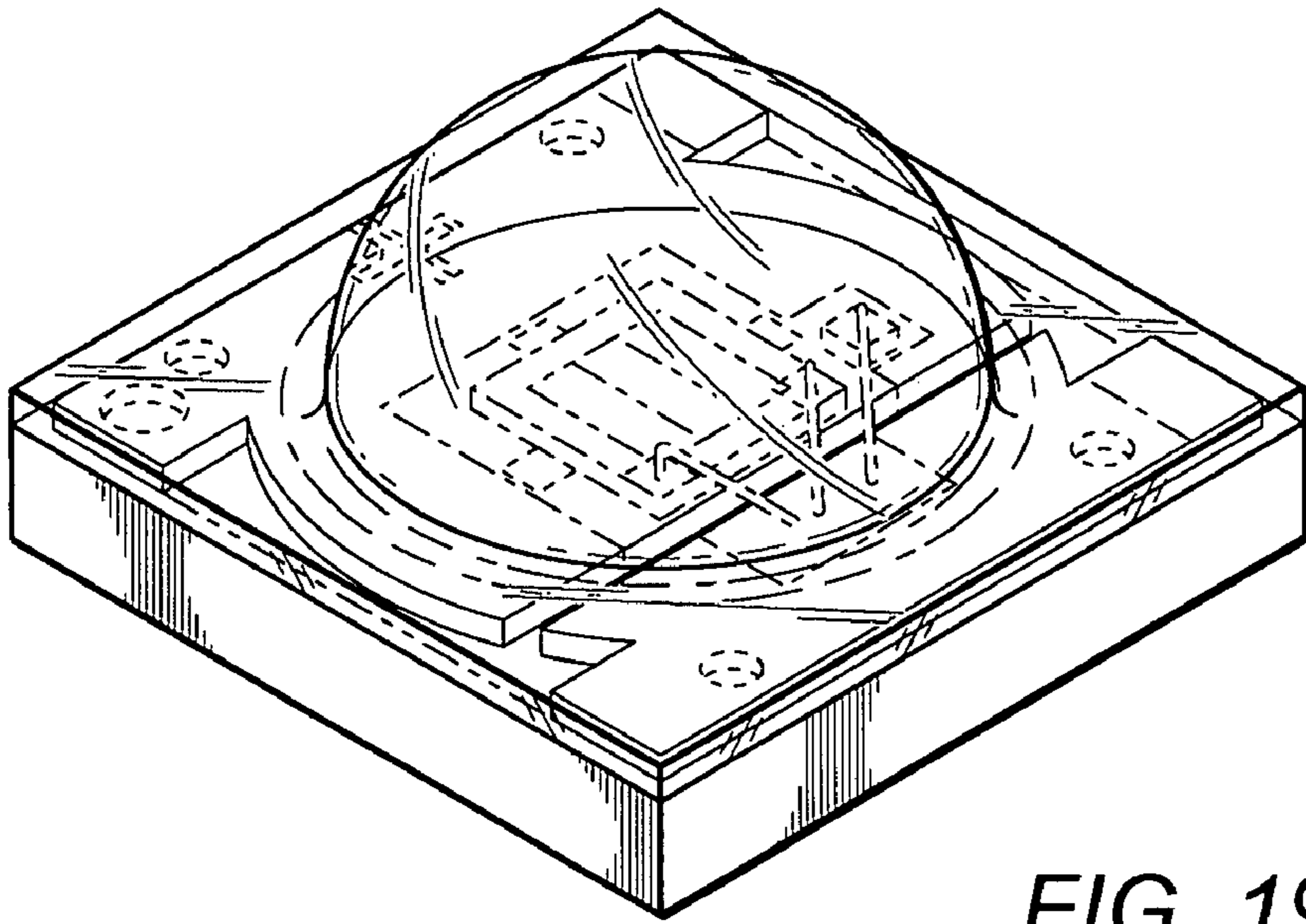


FIG. 19

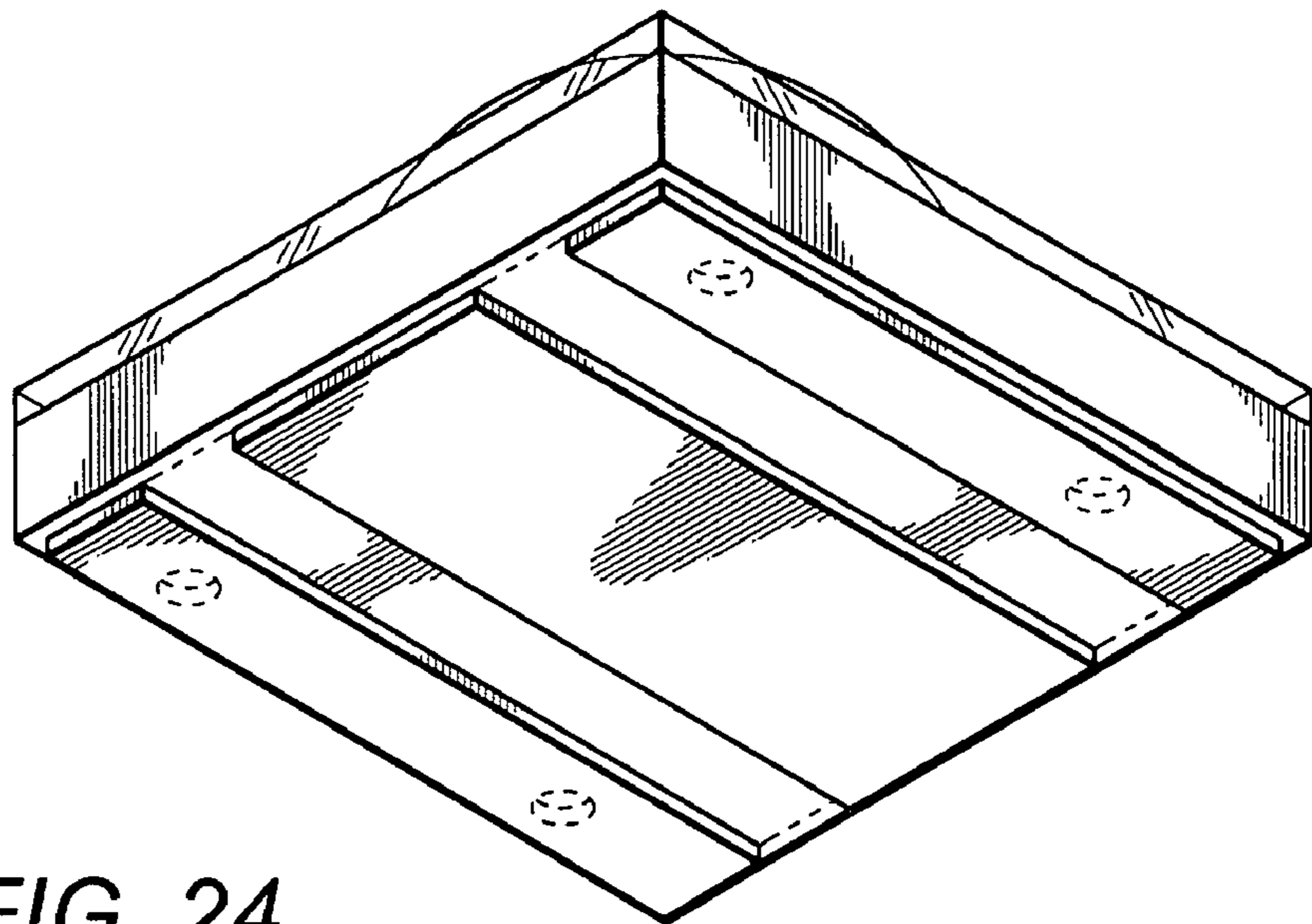
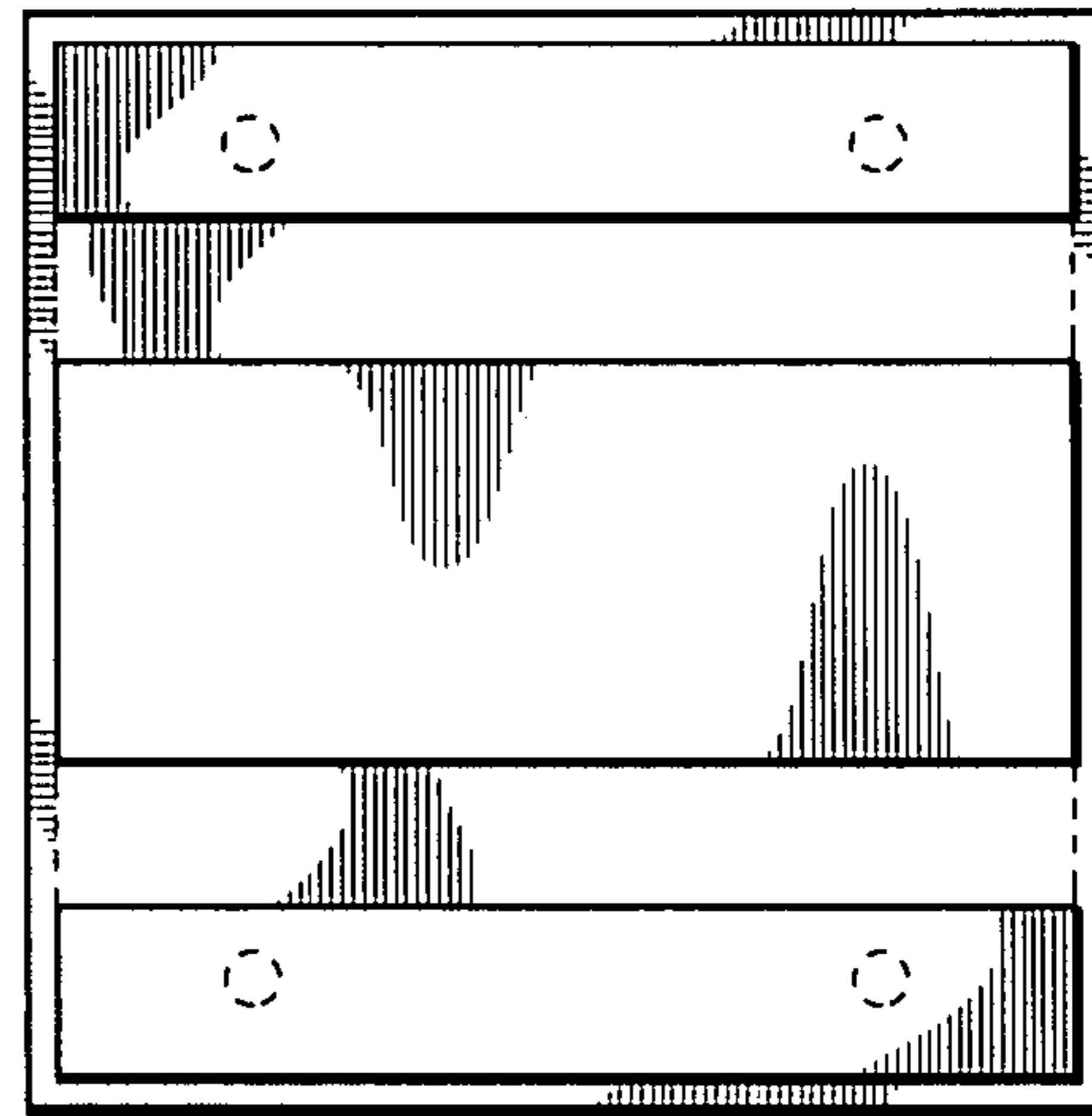
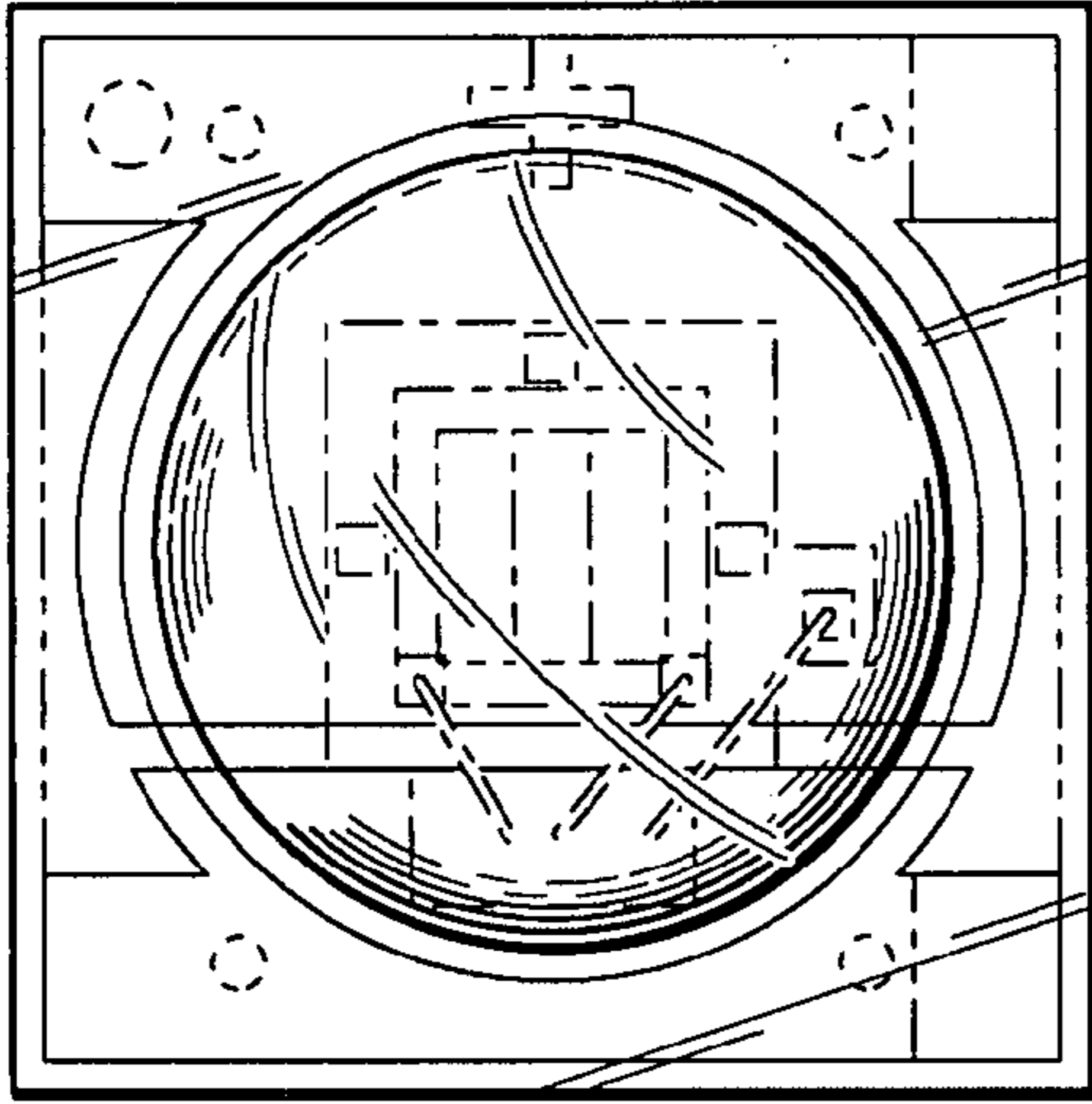
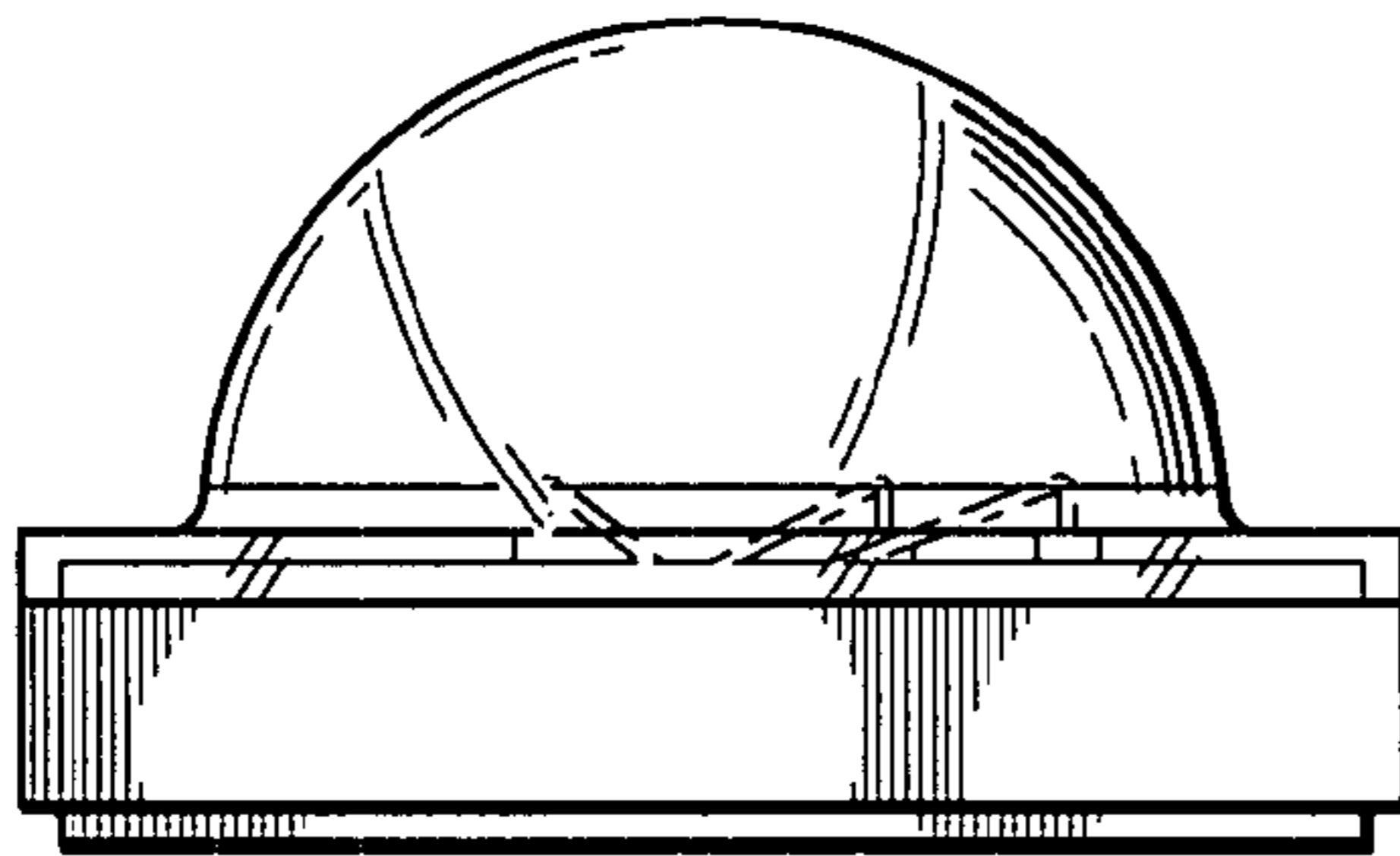


FIG. 24

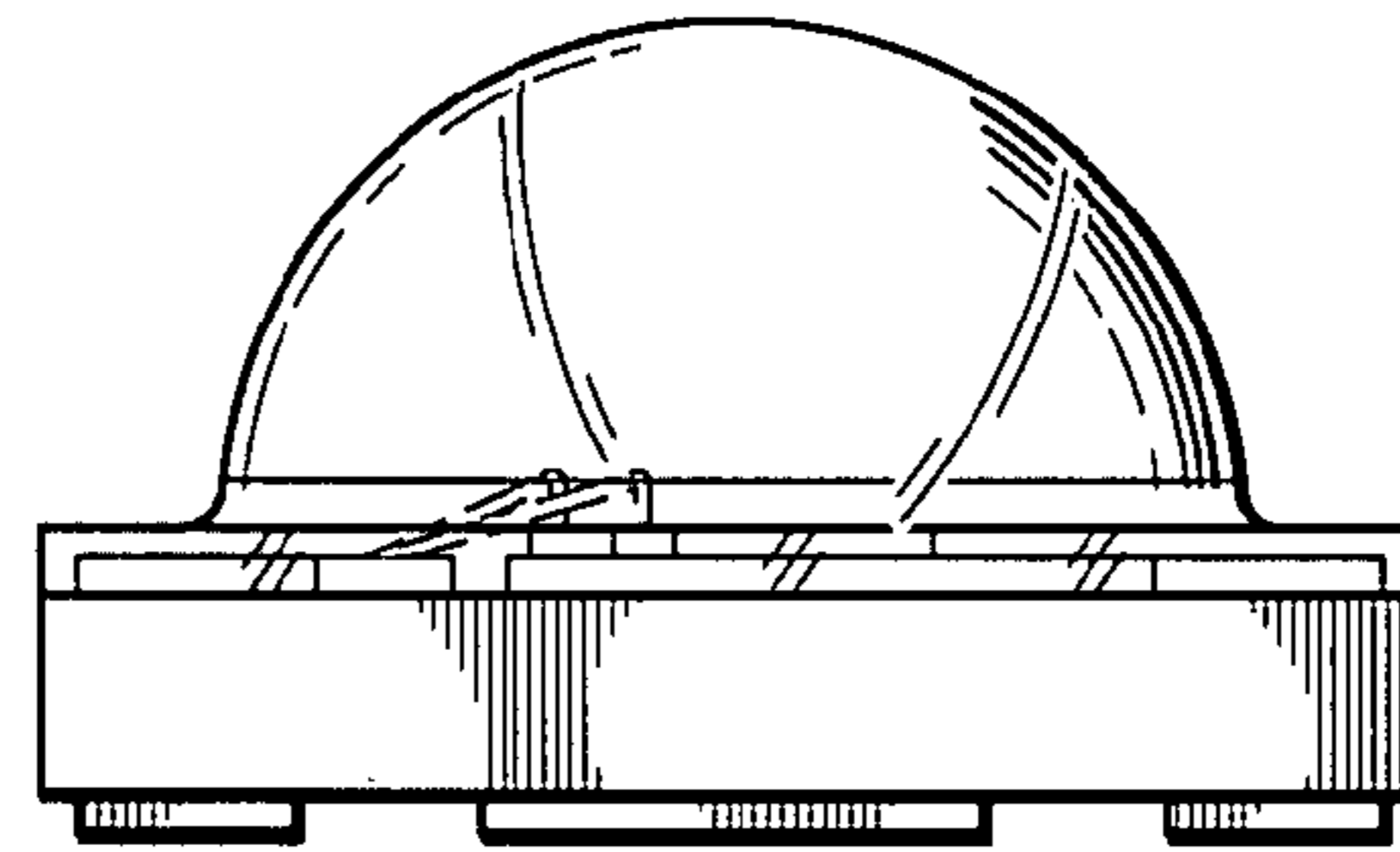
*FIG. 20*



*FIG. 21*



*FIG. 22*



*FIG. 23*

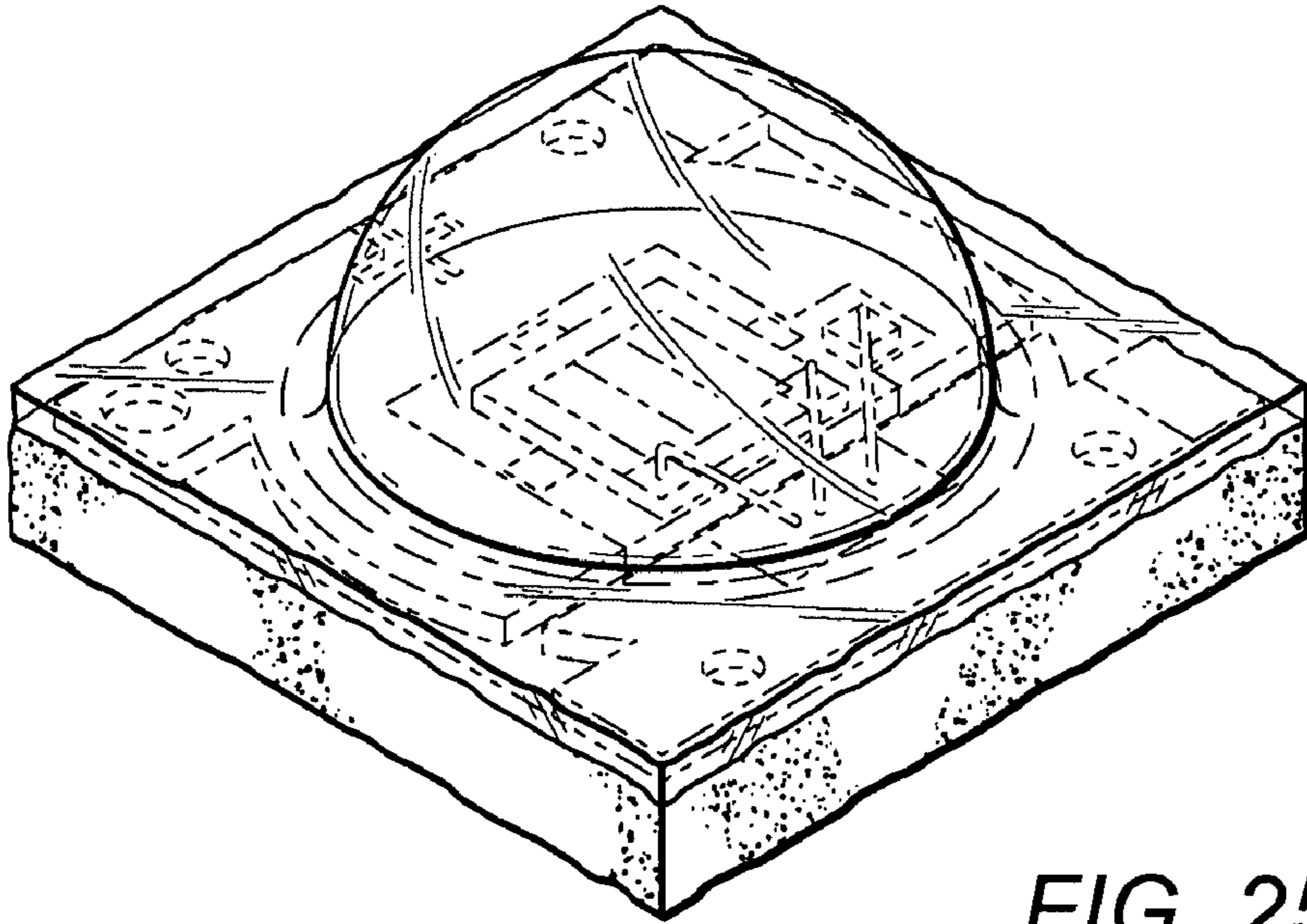


FIG. 25

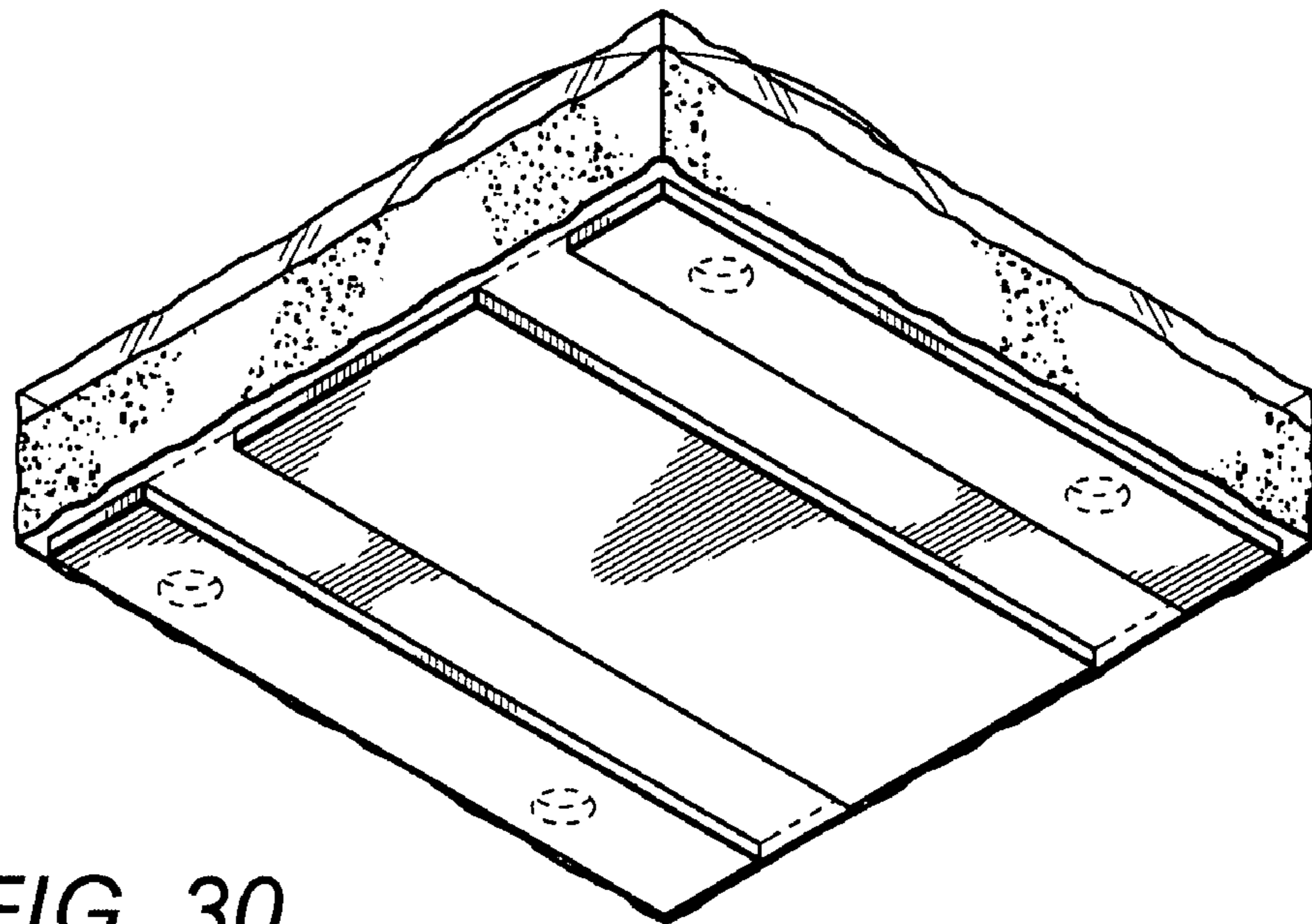


FIG. 30

FIG. 26

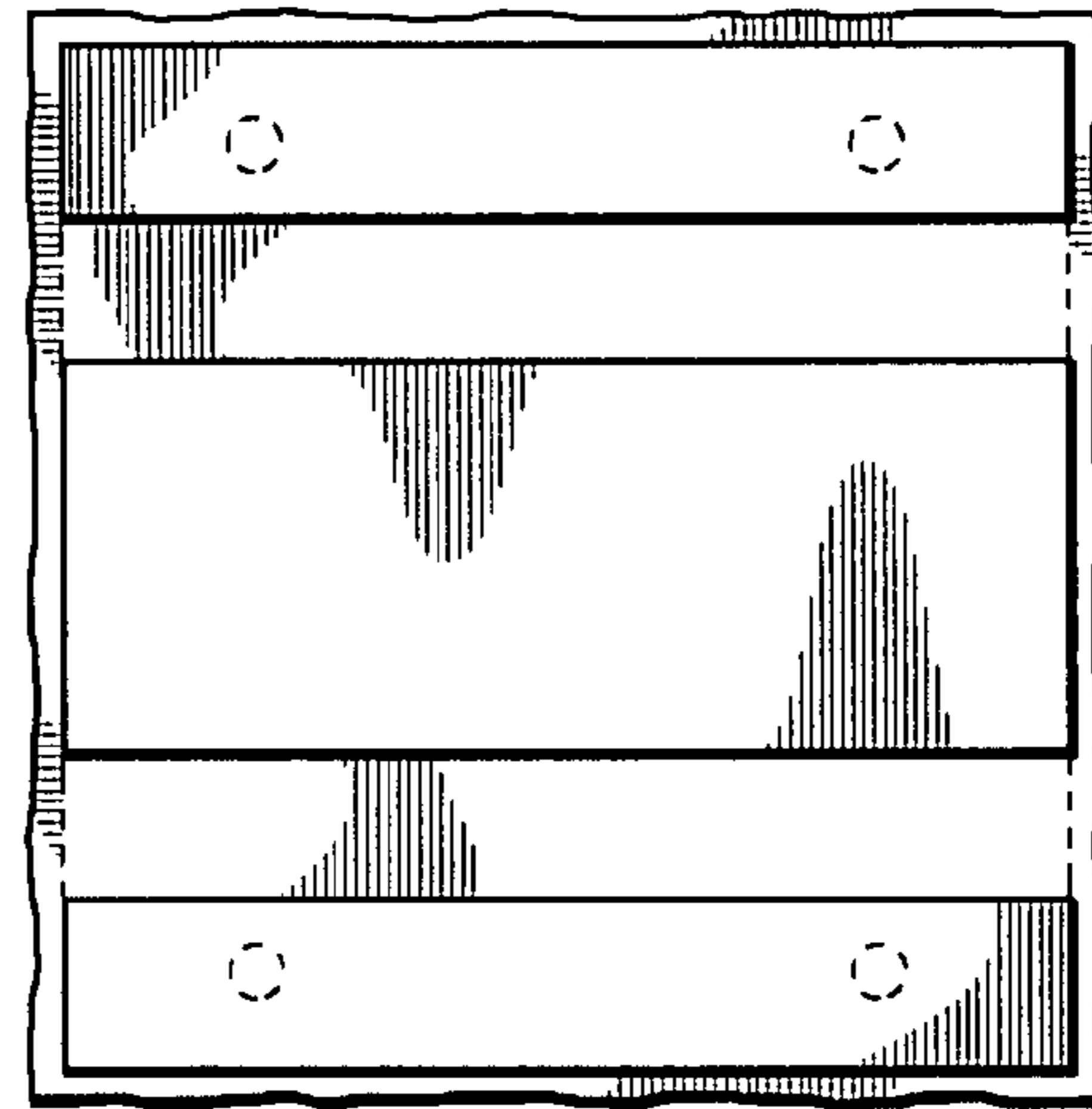
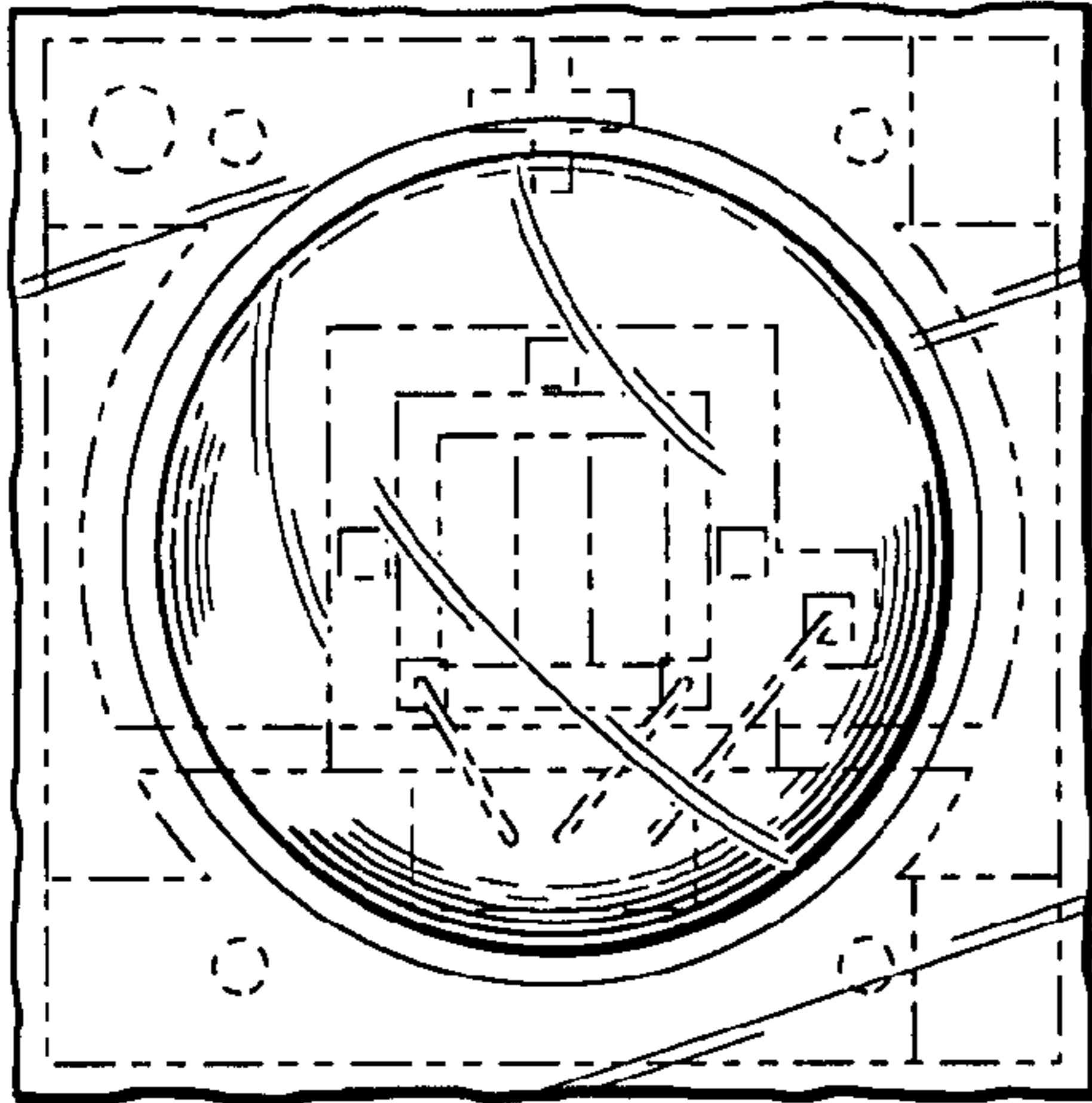


FIG. 27

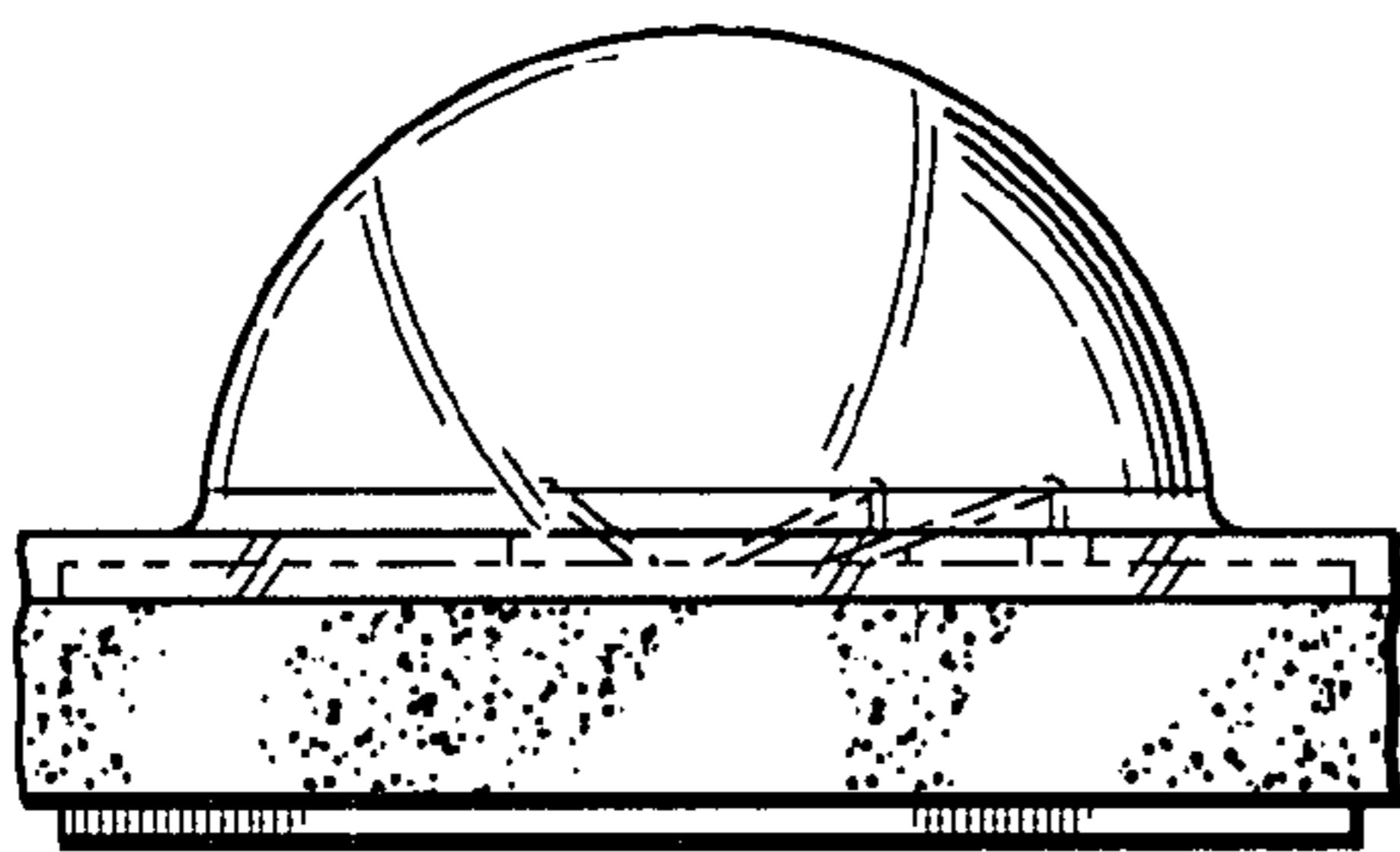


FIG. 28

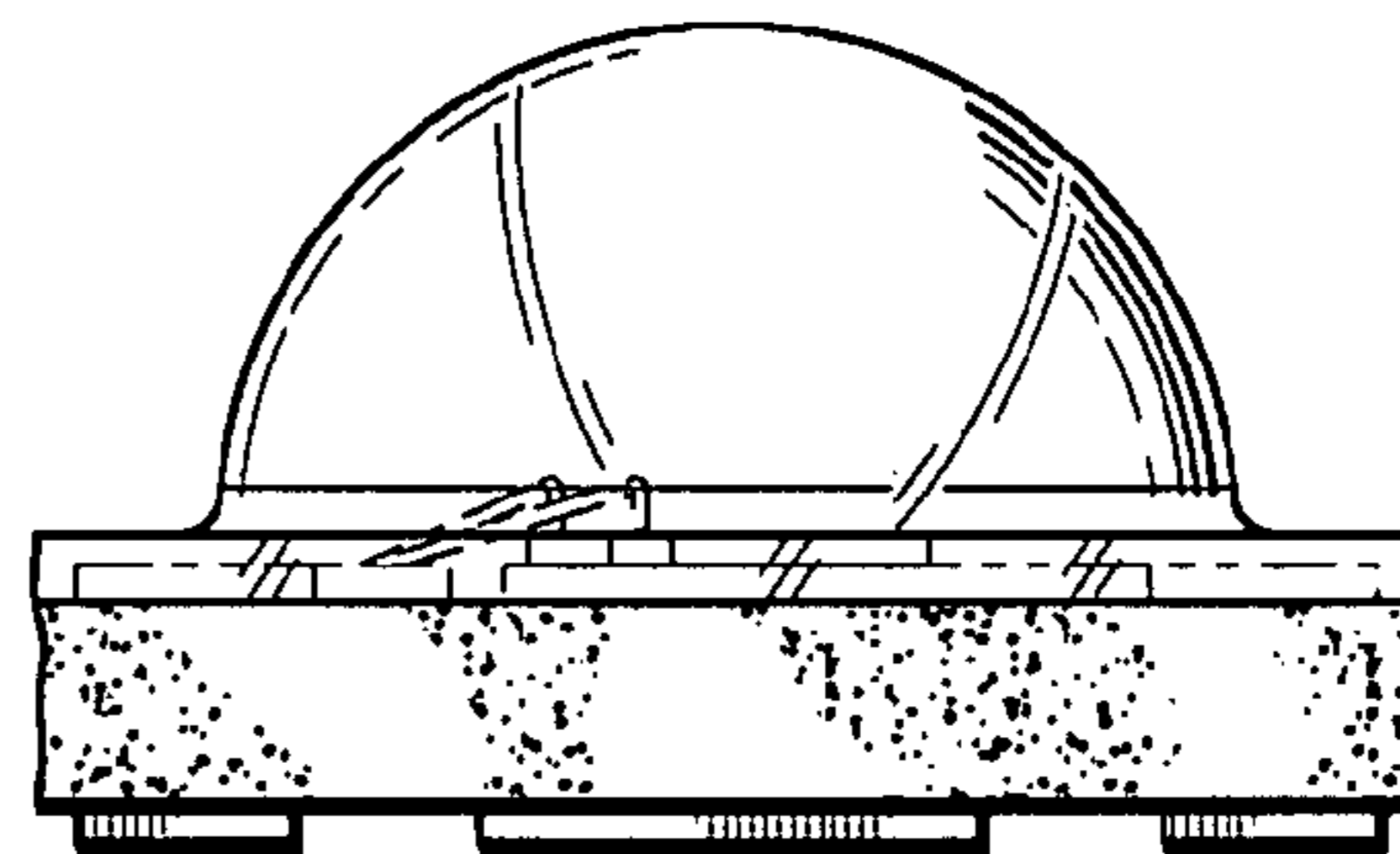


FIG. 29

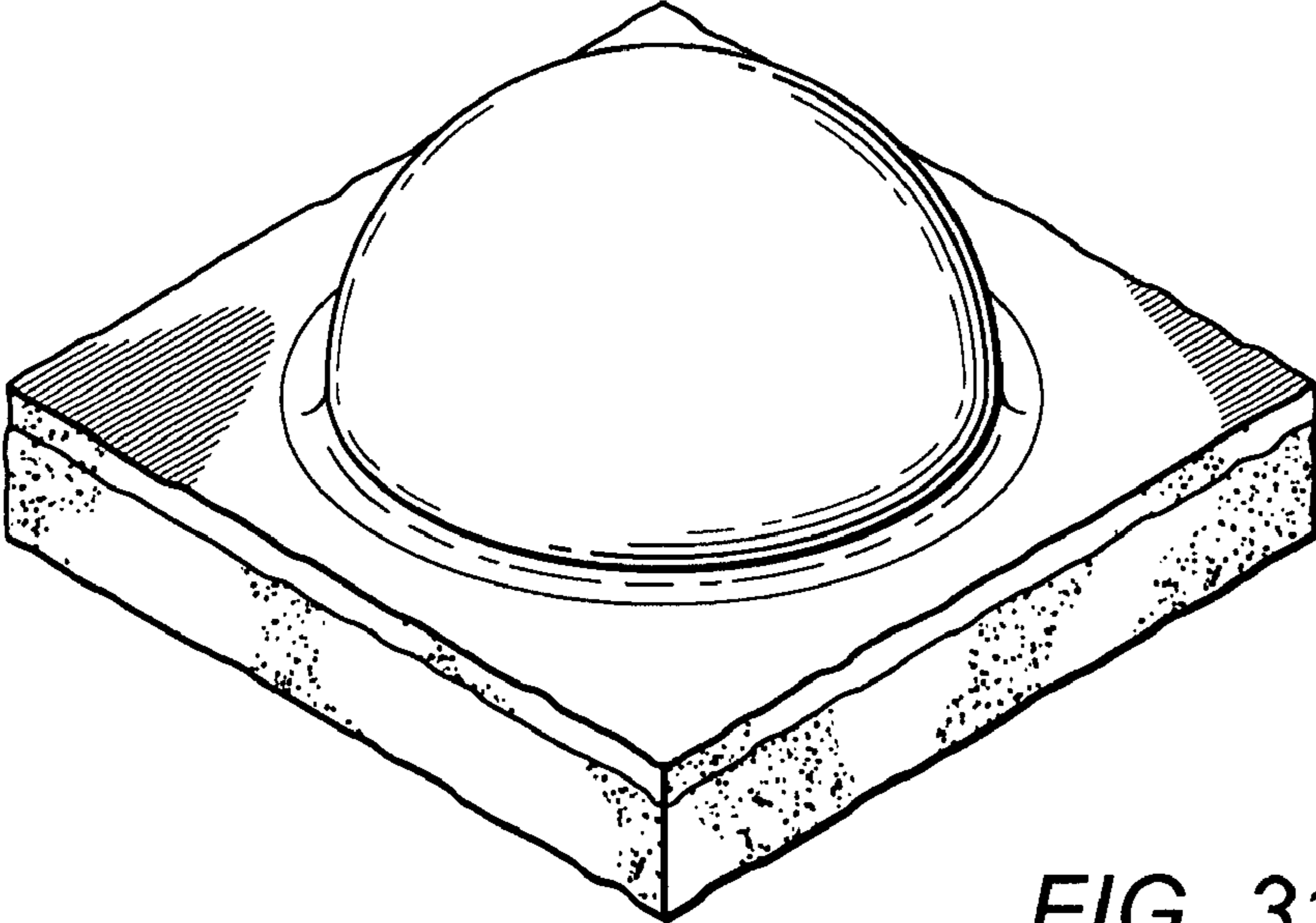


FIG. 31

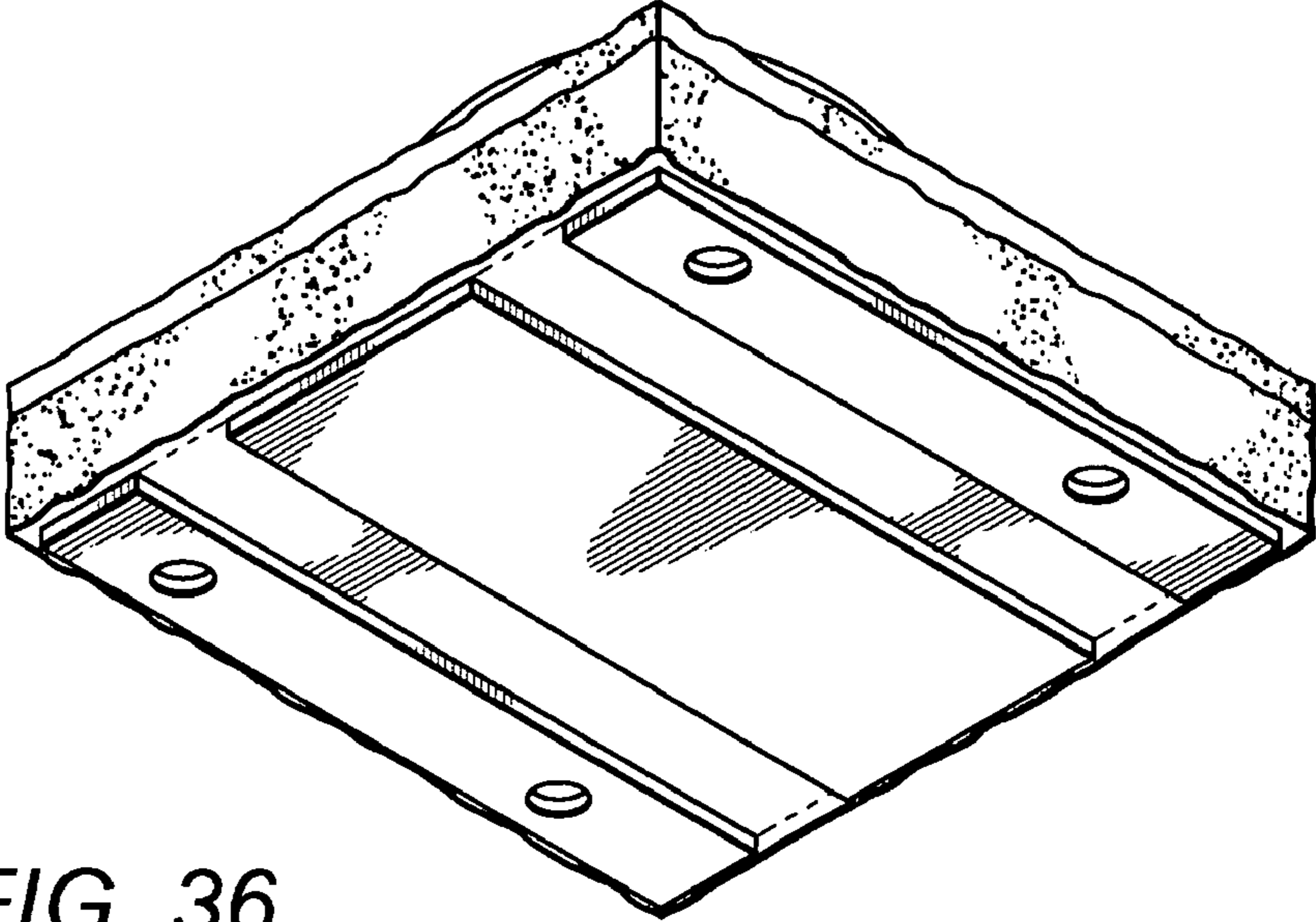


FIG. 36

FIG. 32

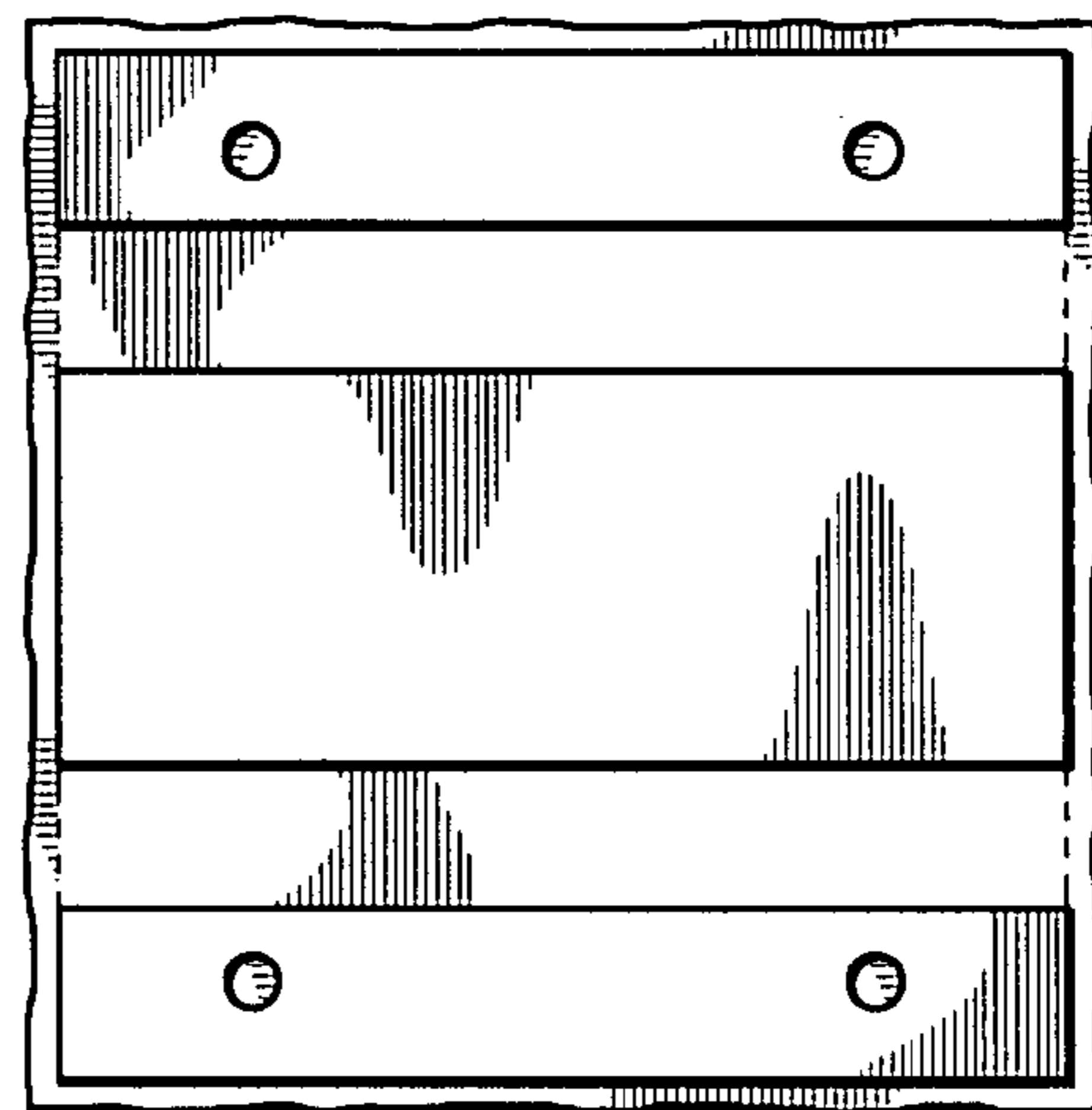
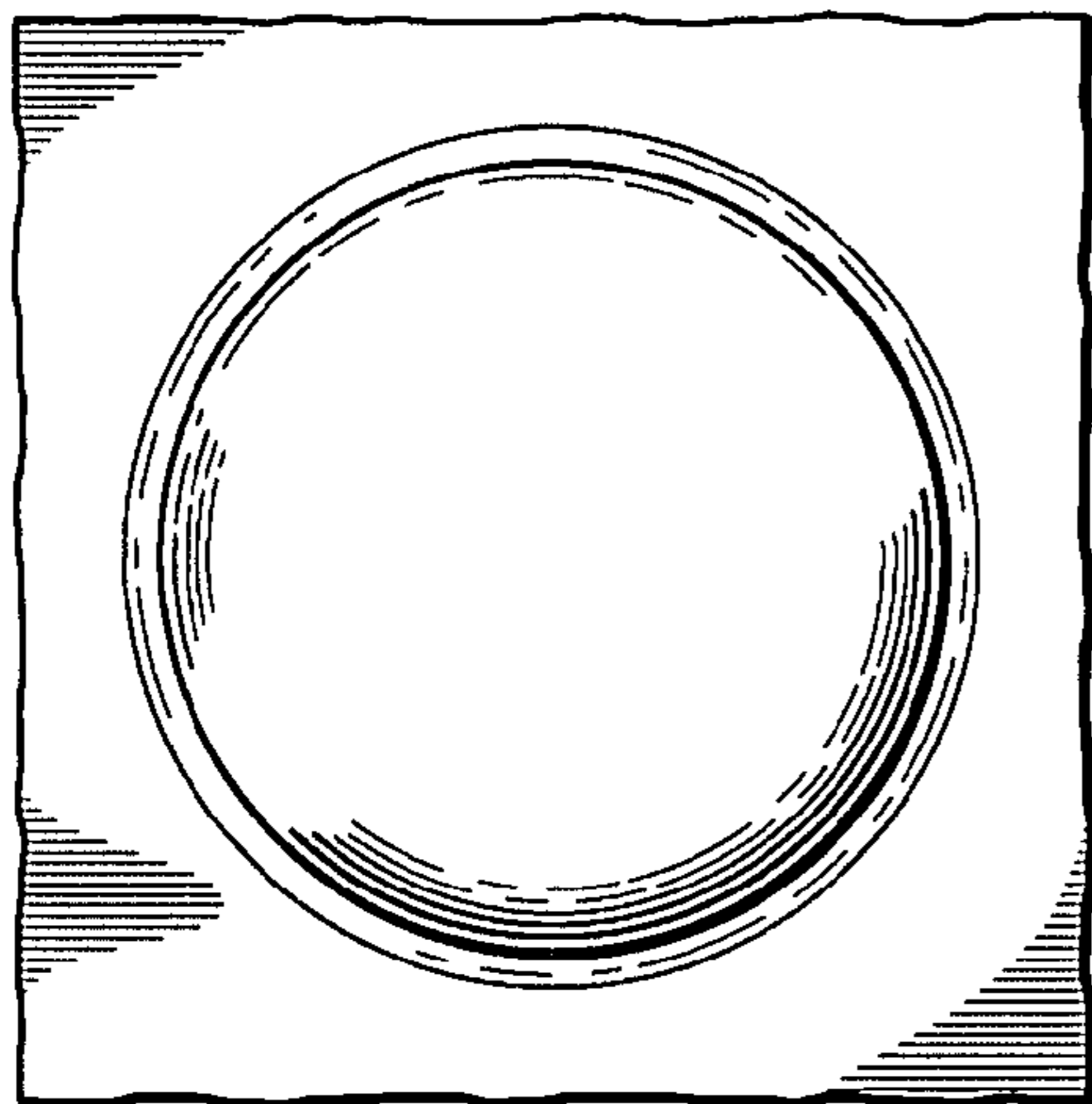


FIG. 33

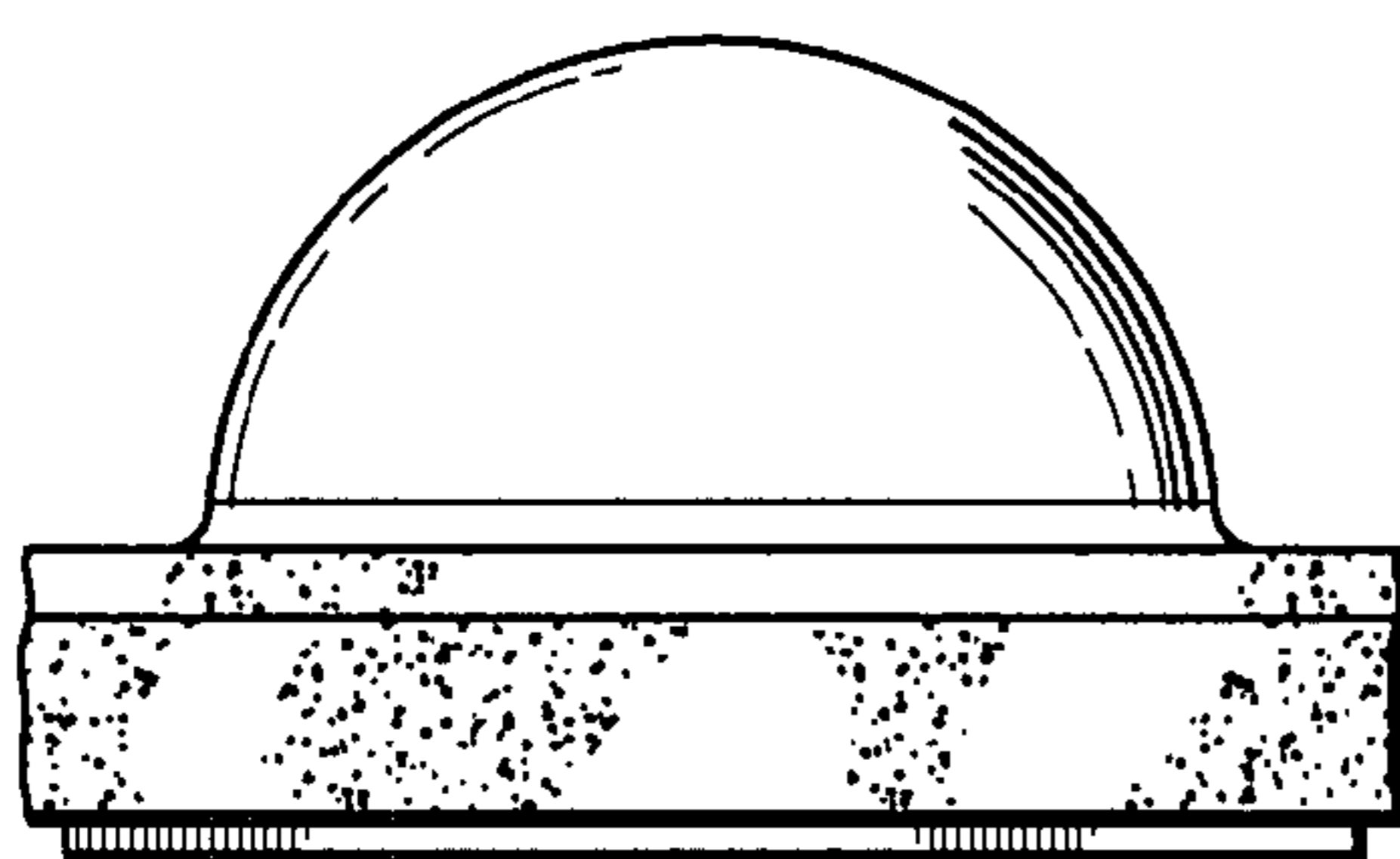


FIG. 34

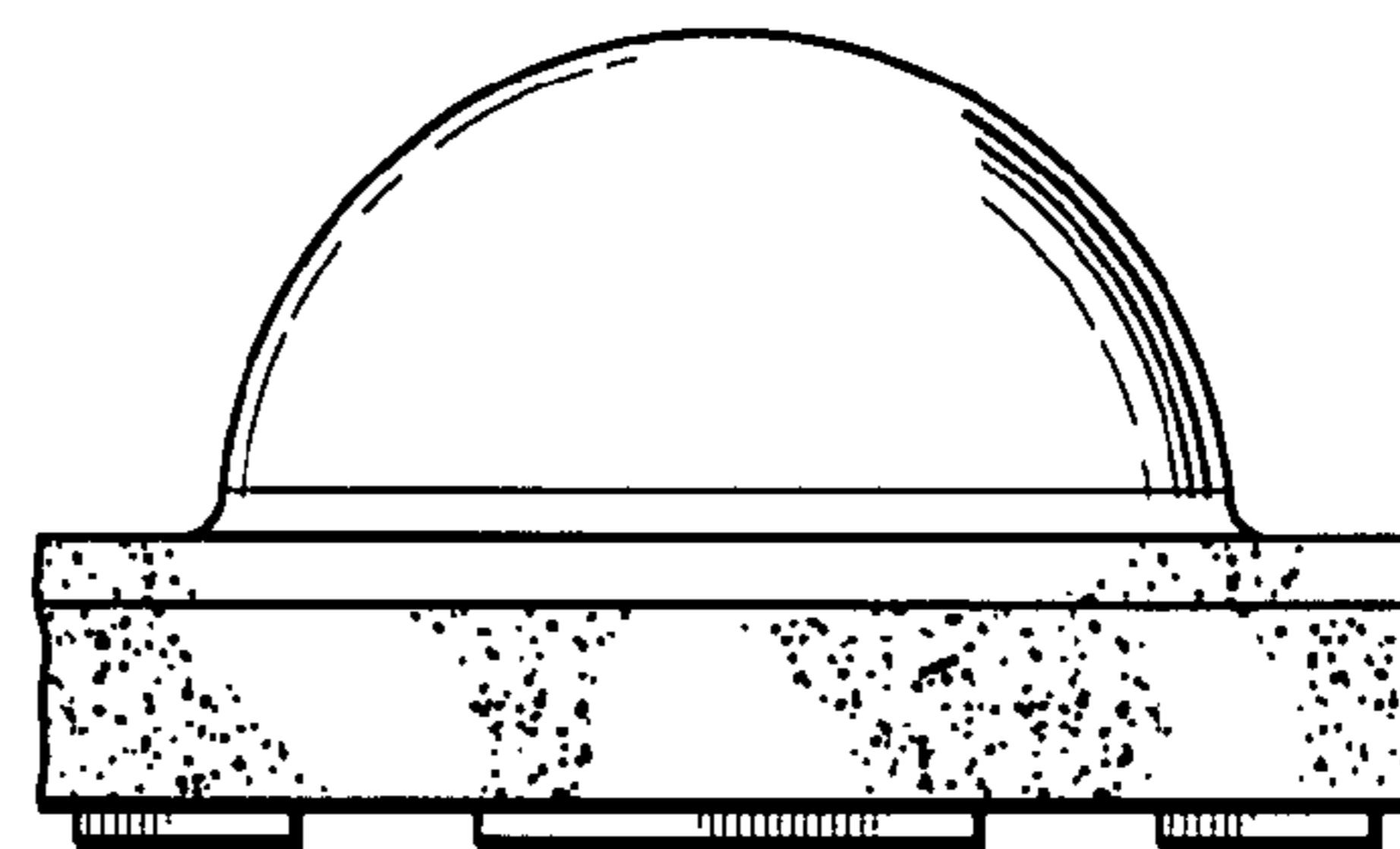


FIG. 35